



# REALTEK

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**RTL8367SCI-CG**

## **LAYER 2 MANAGED 5+2-PORT 10/100/1000M SWITCH CONTROLLER**

### **DATASHEET**

**(CONFIDENTIAL: Development Partners Only)**

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## **USING THIS DOCUMENT**

This document is intended for the hardware and software engineer’s general information on the Realtek RTL8367SCI IC.

Though every effort has been made to ensure that this document is current and accurate, more information may have become available subsequent to the production of this guide.

## **ELECTROSTATIC DISCHARGE (ESD) WARNING**

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- Use a conductive wrist strap attached to a good earth ground
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- If working on a prototyping board, use a soldering iron or station that is marked as ESD-safe
- Always disconnect the microcontroller from the prototyping board when it is being worked on

## **REVISION HISTORY**

Revision	Release Date	Summary
1.0	2023/03/09	First release.
1.1	2024/03/15	Revised section 5 Block Diagram, page 7. Revised Pin 91 in Table 1, Table 8, Table 10, and Table 11. Revised section 12.3 Thermal Characteristics, page 55. Revised section 12.6 Power and Reset Characteristics, page 74. Revised section 13 Mechanical Dimensions, page 75. Corrected minor typing errors.

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## 1. General Description

The RTL8367SCI-CG is an industrial grade E-pad LQFP 128-pin, high-performance 5+2-port 10/100/1000M Ethernet switch featuring a low-power integrated 5-port Giga-PHY that supports 1000Base-T, 100Base-TX, and 10Base-T in industrial and factory applications.

For specific applications, the RTL8367SCI supports two extra interfaces that could be configured as HSGMII/SGMII interfaces. The RTL8367SCI integrates all the functions of a high-speed switch system; including SRAM for packet buffering, non-blocking switch fabric, and internal register management into a single CMOS device. Only a 25MHz crystal is required; an optional EEPROM is offered for internal register configuration.

The embedded packet storage SRAM in the RTL8367SCI features superior memory management technology to efficiently utilize memory space. The RTL8367SCI integrates a 2K-entry look-up table with a 4-way XOR Hashing algorithm for address searching and learning. The table provides read/write access from the EEPROM Serial Management Interface (SMI), Media Independent Interface Management (MIIM), or SPI Interface. Each of the table entries can be configured as a static entry. The entry aging time is between 200 and 400 seconds. Four Filtering Databases are used to provide Independent VLAN Learning and Shared VLAN Learning (IVL/SVL) functions.

The Extension MAC1 and Extension MAC2 of the RTL8367SCI implement HSGMII/SGMII/RGMII/MII interfaces. These interfaces could be connected to an external PHY, MAC, CPU, or RISC for specific applications. In router applications, the RTL8367SCI supports Port VID (PVID) for each port to insert a PVID in the VLAN tag on egress. When using this function, VID information carried in the VLAN tag will be changed to PVID.

The RTL8367SCI supports standard 802.3x flow control frames for full duplex, and optional backpressure for half duplex. It determines when to invoke the flow control mechanism by checking the availability of system resources, including the packet buffers and transmitting queues. The RTL8367SCI supports broadcast/multicast output dropping, and will forward broadcast/multicast packets to non-blocked ports only.

In order to support flexible traffic classification, the RTL8367SCI supports 64-entry ACL rule check and multiple actions options. Each port can optionally enable or disable the ACL rule check function. The ACL rule key can be based on packet physical port, Layer2, Layer3, and Layer4 information. When an ACL rule matches, the action taken is configurable to Drop/Permit/Redirect/Mirror, change priority value in 802.1q/Q tag, force output tag format and rate policing. The rate policing mechanism supports from 8Kbps to 2.5Gbps (in 8Kbps steps).



In Bridge operation the RTL8367SCI supports 4 sets of port configurations: disable, block, learning, and forwarding for Spanning Tree Protocol and Multiple Spanning Tree Protocol. To meet security and management application requirements, the RTL8367SCI supports IEEE 802.1x Port-based Access Control. A 1-set Port Mirroring function is configured to mirror traffic (RX, TX, or both) appearing on one of the switch's ports. Support is provided on each port for multiple RFC MIB Counters, for easy debug and diagnostics.

To improve real-time or multimedia networking applications, the RTL8367SCI supports five priority assignments for each received packet. These are based on (1) Port-based priority; (2) 802.1p/Q VLAN tag priority; (3) DSCP field in IPv4/IPv6 header; (4) ACL-assigned priority and (5) SVLAN tag priority. Each output port supports a weighted ratio of eight priority queues to fit bandwidth requirements in different applications. The input bandwidth control function helps limit per-port traffic utilization. There is one leaky bucket for average packet rate control for each queue of all ports. Queue scheduling algorithm can use Strict Priority (SP) or Weighted Fair Queue (WFQ) or mixed.

The RTL8367SCI provides a 4K-entry VLAN table for 802.1Q port-based and tag-based VLAN operation to separate logical connectivity from physical connectivity. Each port may be set to any topology via EEPROM upon reset, or EEPROM SMI Slave after reset.

In router applications, the router may want to know the input port of the incoming packet. The RTL8367SCI supports an option to insert a VLAN tag with VID=Port VID (PVID) on each egress port. The RTL8367SCI also provides an option to admit VLAN tagged packet with a specific PVID only. If this function is enabled, the RTL8367SCI will drop all non-tagged packets and packets with an incorrect PVID.

## 2. Features

- Single-chip 5+2-port 10/100/1000M non-blocking switch architecture
- Embedded 5-port 10/100/1000Base-T PHY
- Each port supports full duplex 10/100/1000M connectivity (half duplex only supported in 10/100M mode)
- Extension MAC1 supports
  - ◆ High Serial Gigabit Media Independent Interface (HSGMII)
  - ◆ Serial Gigabit Media Independent Interface (SGMII)
- Extension MAC2 supports
  - ◆ High Serial Gigabit Media Independent Interface (HSGMII)
  - ◆ Serial Gigabit Media Independent Interface (SGMII)
  - ◆ Reduced Gigabit Media Independent Interface (RGMII)
  - ◆ Media Independent Interface (MII)
- Full-duplex and half-duplex operation with IEEE 802.3x flow control and backpressure
- Supports 2M-bit SRAM for packet buffering
- Supports 9216-byte jumbo packet length forwarding at wire speed
- Realtek Cable Test (RTCT) function
- Supports 64-entry ACL Rules
  - ◆ Search keys support physical port, Layer2, Layer3, and Layer4 information
  - ◆ Actions include mirror, redirect, dropping, priority adjustment, traffic policing, CVLAN decision, and SVLAN assignment GPIO control, force output tag format, interrupt and logging counter
  - ◆ Supports five types of user defined ACL rule format for 64 ACL rules
  - ◆ Optional per-port enable/disable of ACL function
  - ◆ Optional setting of per-port action to take when ACL mismatch
- Supports IEEE 802.1Q VLAN
  - ◆ Supports 4K VLANs
  - ◆ Supports Un-tag definition in each VLAN
  - ◆ Supports VLAN forwarding decision
  - ◆ Port-based and Tag-based VLAN
  - ◆ Per-port and per-VLAN egress VLAN tagging and un-tagging
- Supports IVL, SVL, and IVL/SVL
  - ◆ 2K-entry MAC address table with 4-way hash algorithm
  - ◆ Up to 2K-entry L2/L3 Filtering Database
  - ◆ Per-port MAC learning limitation
  - ◆ System-based MAC learning limitation
- Supports Spanning Tree Port Behavior configuration
  - ◆ IEEE 802.1w Rapid Spanning Tree
  - ◆ IEEE 802.1s Multiple Spanning Tree with up to 4 Spanning Tree instances
- Supports IEEE 802.1x Access Control Protocol
  - ◆ Port-Based Access Control
- Supports Auto protection from Denial-of-Service attacks
- Supports Quality of Service (QoS)
  - ◆ Supports per port Input Bandwidth Control
  - ◆ Traffic classification based on IEEE 802.1p/Q priority definition, physical Port, IP DSCP field, ACL definition and SVLAN based priority

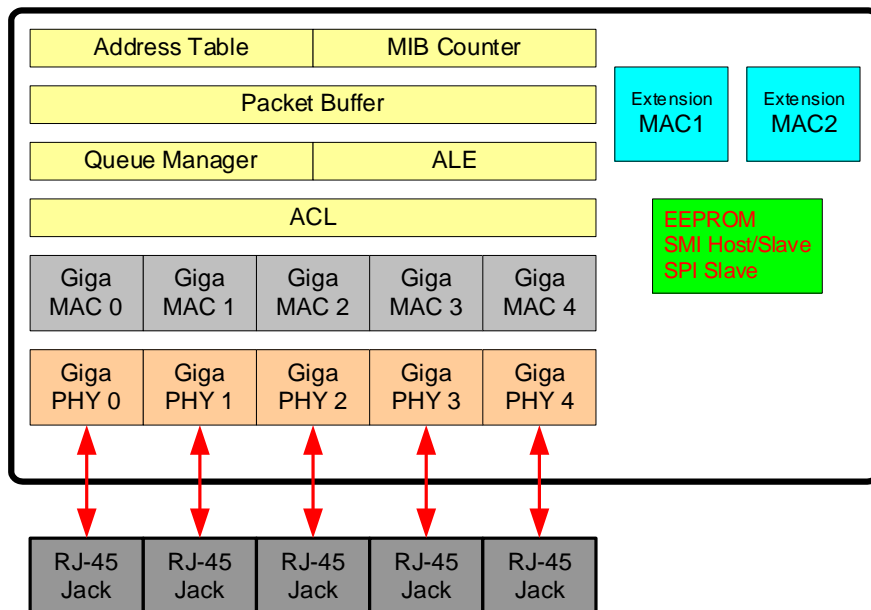
- ◆ Eight Priority Queues per port
- ◆ Per queue flow control
- ◆ Min-Max Scheduling
- ◆ Strict Priority and Weighted Fair Queue (WFQ) to provide minimum bandwidth
- ◆ One leaky bucket to constrain the average packet rate of each queue
- Supports rate limiting (40 shared meters, with 8kbps granulation or packets per second configuration)
- Supports RFC MIB Counter
  - ◆ MIB-II (RFC 1213)
  - ◆ Ethernet-Like MIB (RFC 3635)
  - ◆ Interface Group MIB (RFC 2863)
  - ◆ RMON (RFC 2819)
  - ◆ Bridge MIB (RFC 1493)
  - ◆ Bridge MIB Extension (RFC 2674)
- Supports Stacking VLAN and Port Isolation
- Supports IEEE 802.1ad Stacking VLAN
- Supports two IEEE 802.3ad Link aggregation port groups
- Supports Port Mirror function for one monitor port for multiple mirroring ports
- Supports IEEE LLDP (Energy Efficient Ethernet Link Layer Discovery Protocol)
- Supports Loop Detection
- Security Filtering
- ◆ Disable learning for each port
- ◆ Disable learning-table aging for each port
- ◆ Drop unknown DA for each port
- Broadcast/Multicast/Unknown DA storm control protects system from attack by hackers
- Supports IEEE 802.3az Energy Efficient Ethernet (EEE)
- Supports Realtek Green Ethernet features
  - ◆ Link-Down Power Saving
- Supports one interrupt output to external CPU for notification
- Each port supports 3 LED outputs
- Management Interface Supports
  - ◆ EEPROM SMI Slave interface
  - ◆ Media Independent Interface Management (MIIM)
  - ◆ SPI Slave Interface
- Supports 32K-byte EEPROM space for configuration
- Integrated 8051 microprocessor
- 25MHz crystal or 3.3V OSC input
- Industrial grade manufacturing process
- 14x14 E-pad LQFP 128-pin package

### 3. System Applications

- 5-Port 1000Base-T Switch
- 5-Port 1000Base-T Router with Dual HSGMII/SGMII
- Industrial and factory automation equipment

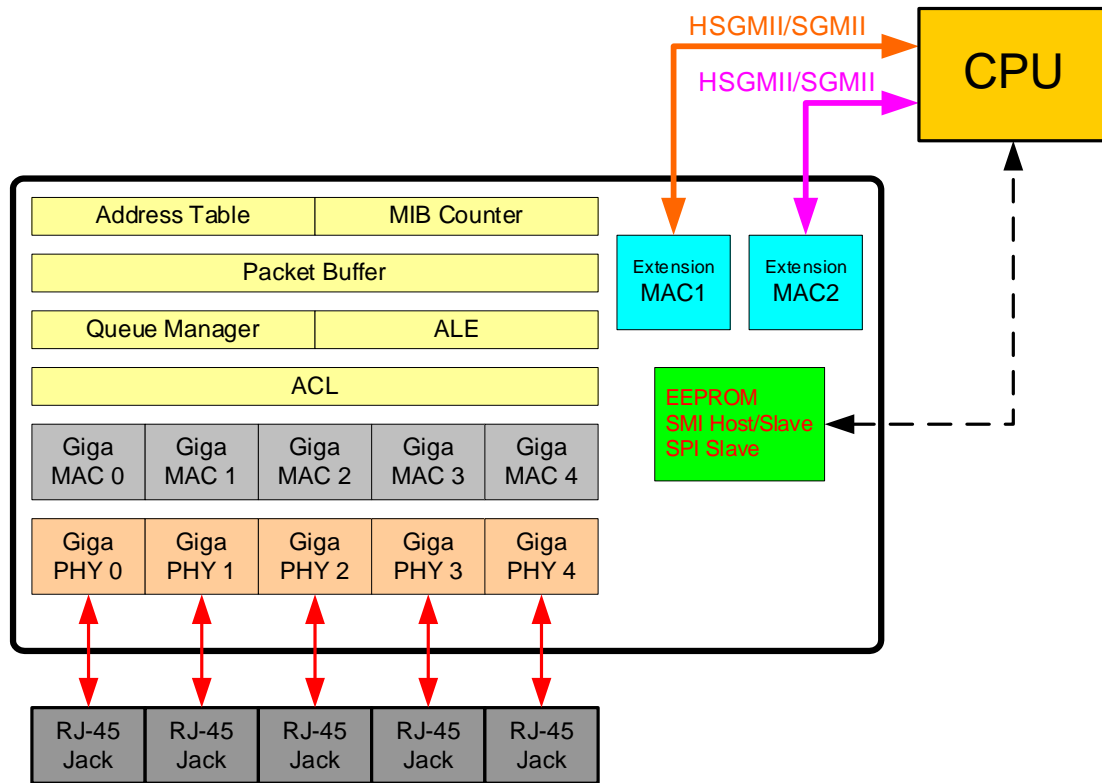
## 4. Application Examples

### 4.1. 5-Port 1000Base-T Switch



**Figure 1. 5-Port 1000Base-T Switch**

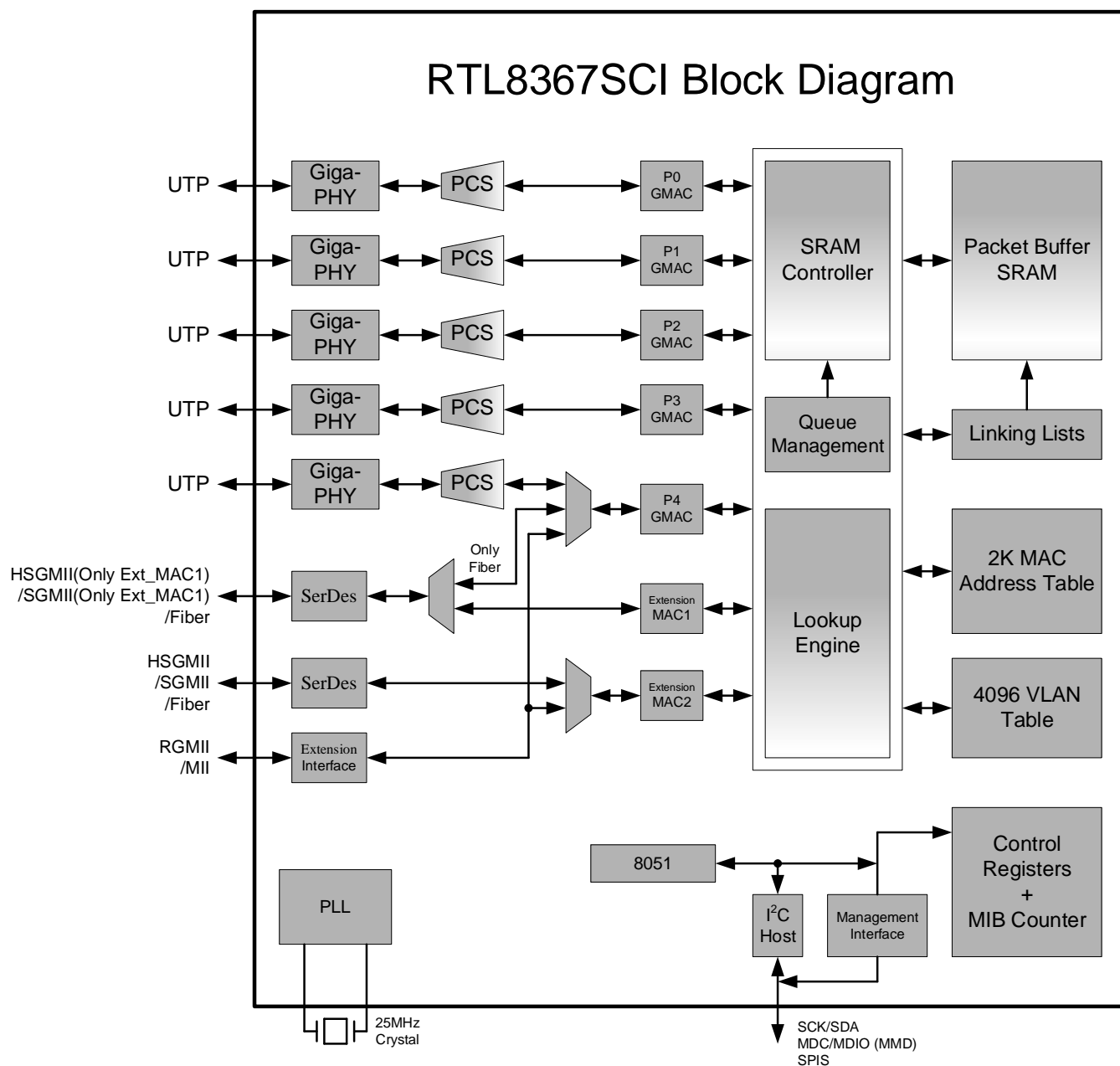
## 4.2. 5-Port 1000Base-T Router with Dual HSGMII/SGMII



**Figure 2. 5-Port 1000Base-T Router with Dual HSGMII/SGMII**

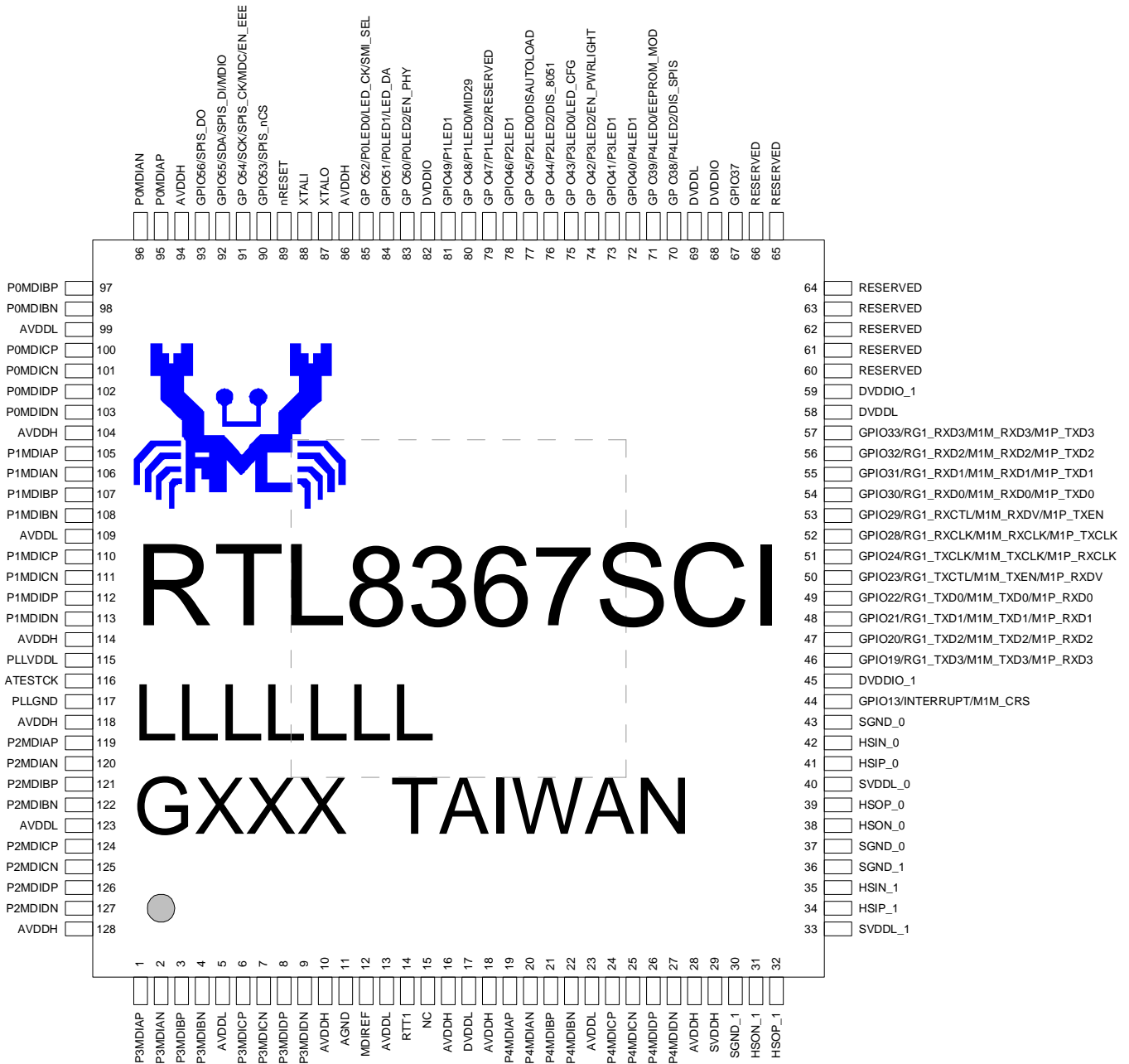
*Note: Extra Interface (Extension MAC1 and Extension MAC2) in HSGMII/SGMII Mode.*

## 5. Block Diagram



**Figure 3. Block Diagram**

## 6. Pin Assignments



E-pad: GND

LQFP 128-pin

Package Size 14mm x 14mm

**Figure 4. Pin Assignments**

### 6.1. Package Identification

Green package is indicated by the 'G' in GXXX (Figure 4).



## 6.2. Pin Assignments Table

Upon Reset: Defined as a short time after the end of a hardware reset.

After Reset: Defined as the time after the specified 'Upon Reset' time.

I: Input Pin

AI: Analog Input Pin

O: Output Pin

AO: Analog Output Pin

I/O: Bi-Directional Input/Output Pin

AI/O: Analog Bi-Directional Input/Output Pin

P: Digital Power Pin

AP: Analog Power Pin

G: Digital Ground Pin

AG: Analog Ground Pin

IPU: Input Pin With Pull-Up Resistor  
(Typical Value = 75K Ohm)

OPU: Output Pin With Pull-Up Resistor  
(Typical Value = 75K Ohm)

I/OPU: Bi-Directional Input/Output Pin  
With Pull-Up Resistor  
(Typical Value = 75K Ohm)

I/OPD: Bi-Directional Input/Output Pin  
With Pull-Down Resistor  
(Typical Value = 75K Ohm)

**Table 1. Pin Assignments Table**

Name	Pin No.	Type
P3MDIAP	1	AI/O
P3MDIAN	2	AI/O
P3MDIBP	3	AI/O
P3MDIBN	4	AI/O
AVDDL	5	AP
P3MDICP	6	AI/O
P3MDICN	7	AI/O
P3MDIDP	8	AI/O
P3MDIDN	9	AI/O
AVDDH	10	AP
AGND	11	AG
MDIREF	12	AO
AVDDL	13	AP
RTT1	14	AO
NC	15	-
AVDDH	16	AP
DVDDL	17	P
AVDDH	18	AP
P4MDIAP	19	AI/O
P4MDIAN	20	AI/O
P4MDIBP	21	AI/O
P4MDIBN	22	AI/O
AVDDL	23	AP
P4MDICP	24	AI/O
P4MDICN	25	AI/O

Name	Pin No.	Type
P4MDIDP	26	AI/O
P4MDIDN	27	AI/O
AVDDH	28	AP
SVDDH	29	AP
SGND_1	30	AG
HSOP_1	31	AO
HSOP_1	32	AO
SVDDL_1	33	AP
HSIP_1	34	AI
HSIN_1	35	AI
SGND_1	36	AG
SGND_0	37	AG
HSOP_0	38	AO
HSOP_0	39	AO
SVDDL_0	40	AP
HSIP_0	41	AI
HSIN_0	42	AI
SGND_0	43	AG
GPIO13/INTERRUPT/M1M_CRS	44	I/OPD
DVDDIO_1	45	P
GPIO19/RG1_TXD3 /M1M_TXD3/M1P_RXD3	46	I/O
GPIO20/RG1_TXD2 /M1M_TXD2/M1P_RXD2	47	I/O
GPIO21/RG1_TXD1 /M1M_TXD1/M1P_RXD1	48	I/O

Name	Pin No.	Type
GPIO22/RG1_TXD0 /M1M_TXD0/M1P_RXD0	49	I/O
GPIO23/RG1_TXCTL /M1M_TXEN/M1P_RXDV	50	I/O
GPIO24/RG1_TXCLK /M1M_TXCLK/M1P_RXCLK	51	I/O
GPIO28/RG1_RXCLK /M1M_RXCLK/M1P_TXCLK	52	I/O
GPIO29/RG1_RXCTL /M1M_RXDV/M1P_TXEN	53	I/O
GPIO30/RG1_RXD0 /M1M_RXD0/M1P_TXD0	54	I/O
GPIO31/RG1_RXD1 /M1M_RXD1/M1P_TXD1	55	I/O
GPIO32/RG1_RXD2 /M1M_RXD2/M1P_TXD2	56	I/O
GPIO33/RG1_RXD3 /M1M_RXD3/M1P_TXD3	57	I/O
DVDDL	58	P
DVDDIO_1	59	P
RESERVED	60	AI
RESERVED	61	AG
RESERVED	62	AG
RESERVED	63	AO
RESERVED	64	AO
RESERVED	65	AP
RESERVED	66	AP
GPIO37	67	I/OPU
DVDDIO	68	P
DVDDL	69	P
GP_O38/P4LED2/DIS_SPIS	70	OPU
GP_O39/P4LED0/EEPROM_MOD	71	OPU
GPIO40/P4LED1	72	I/OPU
GPIO41/P3LED1	73	I/OPU
GP_O42/P3LED2/EN_PWRLIGHT	74	OPU
GP_O43/P3LED0/LED_CFG	75	OPU
GP_O44/P2LED2/DIS_8051	76	OPU
GP_O45/P2LED0/DISAUTOLOAD	77	OPU
GPIO46/P2LED1	78	I/OPU
GP_O47/P1LED2/RESERVED	79	OPU
GP_O48/P1LED0/MID29	80	OPU
GPIO49/P1LED1	81	I/OPU
DVDDIO	82	P
GP_O50/P0LED2/EN_PHY	83	OPU
GPIO51/P0LED1/LED_DA	84	I/OPU
GP_O52/P0LED0/LED_CK /SMI_SEL	85	OPU

Name	Pin No.	Type
AVDDH	86	AP
XTALO	87	AO
XTALI	88	AI
nRESET	89	Ipu
GPIO53/SPIS_nCS	90	I/OPU
GP_O54/SCK/SPIS_CK/MDC /EN_EEE	91	O
GPIO55/SDA/SPIS_DI/MDIO	92	I/O
GPIO56/SPIS_DO	93	I/O
AVDDH	94	AP
P0MDIAP	95	AI/O
P0MDIAN	96	AI/O
P0MDIBP	97	AI/O
P0MDIBN	98	AI/O
AVDDL	99	AP
P0MDICP	100	AI/O
P0MDICN	101	AI/O
P0MDIDP	102	AI/O
P0MDIDN	103	AI/O
AVDDH	104	AP
P1MDIAP	105	AI/O
P1MDIAN	106	AI/O
P1MDIBP	107	AI/O
P1MDIBN	108	AI/O
AVDDL	109	AP
P1MDICP	110	AI/O
P1MDICN	111	AI/O
P1MDIDP	112	AI/O
P1MDIDN	113	AI/O
AVDDH	114	AP
PLLVDL	115	AP
ATESTCK	116	AO
PLLGND	117	AG
AVDDH	118	AP
P2MDIAP	119	AI/O
P2MDIAN	120	AI/O
P2MDIBP	121	AI/O
P2MDIBN	122	AI/O
AVDDL	123	AP
P2MDICP	124	AI/O
P2MDICN	125	AI/O
P2MDIDP	126	AI/O
P2MDIDN	127	AI/O
AVDDH	128	AP
GND	E-pad	G

## 7. Pin Descriptions

### 7.1. Media Dependent Interface Pins

**Table 2. Media Dependent Interface Pins**

Pin Name	Pin No.	Type	Drive (mA)	Description
P0MDIAP	95	AI/O	10	Port 0 Media Dependent Interface A~D. For 1000Base-T operation, differential data from the media is transmitted and received on all four pairs. For 100Base-TX and 10Base-T operation, only MDIAP/N and MDIBP/N are used. Auto MDIX can reverse the pairs MDIAP/N and MDIBP/N. Each of the differential pairs has an internal 100-ohm termination resistor.
P0MDIAN	96			
P0MDIBP	97			
P0MDIBN	98			
P0MDICP	100			
P0MDICN	101			
P0MDIDP	102			
P0MDIDN	103			
P1MDIAP	105	AI/O	10	Port 1 Media Dependent Interface A~D. For 1000Base-T operation, differential data from the media is transmitted and received on all four pairs. For 100Base-TX and 10Base-T operation, only MDIAP/N and MDIBP/N are used. Auto MDIX can reverse the pairs MDIAP/N and MDIBP/N. Each of the differential pairs has an internal 100-ohm termination resistor.
P1MDIAN	106			
P1MDIBP	107			
P1MDIBN	108			
P1MDICP	110			
P1MDICN	111			
P1MDIDP	112			
P1MDIDN	113			
P2MDIAP	119	AI/O	10	Port 2 Media Dependent Interface A~D. For 1000Base-T operation, differential data from the media is transmitted and received on all four pairs. For 100Base-TX and 10Base-T operation, only MDIAP/N and MDIBP/N are used. Auto MDIX can reverse the pairs MDIAP/N and MDIBP/N. Each of the differential pairs has an internal 100-ohm termination resistor.
P2MDIAN	120			
P2MDIBP	121			
P2MDIBN	122			
P2MDICP	124			
P2MDICN	125			
P2MDIDP	126			
P2MDIDN	127			
P3MDIAP	1	AI/O	10	Port 3 Media Dependent Interface A~D. For 1000Base-T operation, differential data from the media is transmitted and received on all four pairs. For 100Base-TX and 10Base-T operation, only MDIAP/N and MDIBP/N are used. Auto MDIX can reverse the pairs MDIAP/N and MDIBP/N. Each of the differential pairs has an internal 100-ohm termination resistor.
P3MDIAN	2			
P3MDIBP	3			
P3MDIBN	4			
P3MDICP	6			
P3MDICN	7			
P3MDIDP	8			
P3MDIDN	9			
P4MDIAP	19	AI/O	10	Port 4 Media Dependent Interface A~D. For 1000Base-T operation, differential data from the media is transmitted and received on all four pairs. For 100Base-TX and 10Base-T operation, only MDIAP/N and MDIBP/N are used. Auto MDIX can reverse the pairs MDIAP/N and MDIBP/N. Each of the differential pairs has an internal 100-ohm termination resistor.
P4MDIAN	20			
P4MDIBP	21			
P4MDIBN	22			
P4MDICP	24			
P4MDICN	25			
P4MDIDP	26			
P4MDIDN	27			

## 7.2. High Speed Serial Interface Pins

**Table 3. High Speed Serial Interface Pins**

Pin Name	Pin No.	Type	Drive (mA)	Description
HSOP_1	31	AO	10	High Speed Serial Output Pins: 3.125GHz/1.25GHz Differential serial interface to transmit data. Keep floating when unused.
HSOP_1	32			
HSIP_1	34	AI	10	High Speed Serial Input Pins: 3.125GHz/1.25GHz Differential serial interface to receive data. Keep floating when unused.
HSIN_1	35			
HSOP_0	38	AO	10	High Speed Serial Output Pins: 3.125GHz/1.25GHz Differential serial interface to transmit data. Keep floating when unused.
HSOP_0	39			
HSIP_0	41	AI	10	High Speed Serial Input Pins: 3.125GHz/1.25GHz Differential serial interface to receive data. Keep floating when unused.
HSIN_0	42			

## 7.3. General Purpose Interfaces

The RTL8367SCI supports multi-function General Purpose Interfaces that can be configured as RGMII/MII mode for extension interface. The RTL8367SCI supports one extension interface (Extension MAC2) for connecting with an external PHY, MAC, or CPU in specific applications. These extension interfaces support RGMII, MII MAC mode, or MII PHY mode via register configuration.

**Table 4. General Purpose Interfaces Pins**

Pin No.	GPIO	RGMII	MII MAC Mode	MII PHY Mode	Other function	Configuration Strapping
44	GPIO13	-	M1M_CRS	-	INTERRUPT	-
46	GPIO19	RG1_TXD3	M1M_TXD3	M1P_RXD3	-	-
47	GPIO20	RG1_TXD2	M1M_TXD2	M1P_RXD2	-	-
48	GPIO21	RG1_TXD1	M1M_TXD1	M1P_RXD1	-	-
49	GPIO22	RG1_TXD0	M1M_TXD0	M1P_RXD0	-	-
50	GPIO23	RG1_TXCTL	M1M_TXEN	M1P_RXDV	-	-
51	GPIO24	RG1_TXCLK	M1M_TXCLK	M1P_RXCLK	-	-
52	GPIO28	RG1_RXCLK	M1M_RXCLK	M1P_TXCLK	-	-
53	GPIO29	RG1_RXCTL	M1M_RXDV	M1P_TXEN	-	-
54	GPIO30	RG1_RXD0	M1M_RXD0	M1P_TXD0	-	-
55	GPIO31	RG1_RXD1	M1M_RXD1	M1P_TXD1	-	-
56	GPIO32	RG1_RXD2	M1M_RXD2	M1P_TXD2	-	-
57	GPIO33	RG1_RXD3	M1M_RXD3	M1P_TXD3	-	-
67	GPIO37	-	-	-	-	-
70	GP O38	-	-	-	P4LED2	DIS_SPIS
71	GP O39	-	-	-	P4LED0	EEPROM_MOD
72	GPIO40	-	-	-	P4LED1	-
73	GPIO41	-	-	-	P3LED1	-
74	GP O42	-	-	-	P3LED2	EN_PWRLIGHT
75	GP O43	-	-	-	P3LED0	LED_CFG
76	GP O44	-	-	-	P2LED2	DIS_8051
77	GP O45	-	-	-	P2LED0	DISAUTOLOAD

Pin No.	GPIO	RGMII	MII MAC Mode	MII PHY Mode	Other function	Configuration Strapping
78	GPIO46	-	-	-	P2LED1	-
79	GP O47	-	-	-	P1LED2	RESERVED
80	GP O48	-	-	-	P1LED0	MID29
81	GPIO49	-	-	-	P1LED1	-
83	GP O50	-	-	-	P0LED2	EN_PHY
84	GPIO51	-	-	-	P0LED1 /LED_DA	-
85	GP O52	-	-	-	P0LED0 /LED_CK	SMI_SEL
90	GPIO53	-	-	-	SPIS_nCS	-
91	GP O54	-	-	-	SCK /SPIS_CK /MDC	EN_EEE
92	GPIO55	-	-	-	SDA /SPIS_DI /MDIO	-
93	GPIO56	-	-	-	SPIS_DO	-

### 7.3.1. RGMII Pins

The Extension MAC2 of the RTL8367SCI supports one RGMII interface to connect with an external MAC or PHY device when register configuration is set to RGMII mode interface.

**Table 5. Extension MAC2 RGMII Pins**

Pin Name	Pin No.	Type	Drive (mA)	Description
RG1_TXD3 RG1_TXD2 RG1_TXD1 RG1_TXD0	46 47 48 49	O	-	RG1_TXD[3:0] Extension MAC2 RGMII Transmit Data Output. Transmitted data is sent synchronously to RG1_TXCLK.
RG1_TXCTL	50	O	-	RG1_TXCTL Extension MAC2 RGMII Transmit Control Signal Output. The RG1_TXCTL indicates TX_EN at the rising edge of RG1_TXCLK, and TX_ER at the falling edge of RG1_TXCLK. At the RG1_TXCLK falling edge, RG1_TXCTL= TX_EN (XOR) TX_ER.
RG1_TXCLK	51	O	-	RG1_TXCLK Extension MAC2 RGMII Transmit Clock Output. RG1_TXCLK is 125MHz @ 1Gbps, 25MHz @ 100Mbps, and 2.5MHz @ 10Mbps. Used for RG1_TXD[3:0] and RG1_TXCTL synchronization at RG1_TXCLK on both rising and falling edges.
RG1_RXCLK	52	I	-	RG1_RXCLK Extension MAC2 RGMII Receive Clock Input. RG1_RXCLK is 125MHz @ 1Gbps, 25MHz @ 100Mbps, and 2.5MHz @ 10Mbps. Used for RG1_RXD[3:0] and RG1_RXCTL synchronization at both RG1_RXCLK rising and falling edges. This pin must be pulled low with a 1K ohm resistor when not used.
RG1_RXCTL	53	I	-	RG1_RXCTL Extension MAC2 RGMII Receive Control Signal Input. The RG1_RXCTL indicates RX_DV at the rising of RG1_RXCLK and RX_ER at the falling edge of RG1_RXCLK. At RG1_RXCLK falling edge, RG1_RXCTL= RX_DV (XOR) RX_ER. This pin must be pulled low with a 1K ohm resistor when not used.
RG1_RXD0 RG1_RXD1 RG1_RXD2 RG1_RXD3	54 55 56 57	I	-	RG1_RXD[3:0] Extension MAC2 RGMII Receive Data Input. Received data is received synchronously by RG1_RXCLK. These pins must be pulled low with a 1K ohm resistor when not used.

### 7.3.2. MII Pins

The Extension MAC2 of the RTL8367SCI supports one MII interface to connect with an external MAC or PHY device when register configuration is set to MII MAC mode or MII PHY mode interface.

**Table 6. Extension MAC2 MII Pins (MII MAC Mode or MII PHY Mode)**

Pin Name	Pin No.	Type	Drive (mA)	Description
M1M_TXD3 /M1P_RXD3	46	O	-	M1M_TXD[3:0] Extension MAC2 MII MAC Mode Transmit Data Output.
M1M_TXD2 /M1P_RXD2	47			Transmitted data is sent synchronously at the rising edge of M1M_TXCLK.
M1M_TXD1 /M1P_RXD1	48			M1P_RXD[3:0] Extension MAC2 MII PHY Mode Receive Data Output.
M1M_TXD0 /M1P_RXD0	49			Received data is received synchronously at the rising edge of M1P_RXCLK.
M1M_TXEN /M1P_RXDV	50	O	-	M1M_TXEN Extension MAC2 MII MAC Mode Transmit Data Enable Output. Transmit enable that is sent synchronously at the rising edge of M1M_TXCLK. M1P_RXDV Extension MAC2 MII PHY Mode Receive Data Valid Output. Receive Data Valid signal that is sent synchronously at the rising edge of M1P_RXCLK.
M1M_TXCLK /M1P_RXCLK	51	I/O	-	M1M_TXCLK Extension MAC2 MII MAC Mode Transmit Clock Input. In MII 100Mbps, M1M_TXCLK is 25MHz Clock Input. In MII 10Mbps, M1M_TXCLK is 2.5MHz Clock Input. Used to synchronize M1M_TXD[3:0] and M1M_TXEN. M1P_RXCLK Extension MAC2 MII PHY Mode Receive Clock Output. In MII 100Mbps, M1P_RXCLK is 25MHz Clock Output. In MII 10Mbps, M1P_RXCLK is 2.5MHz Clock Output. Used to synchronize M1P_RXD[3:0] and M1P_RXDV. This pin must be pulled low with a 1K ohm resistor when not used.
M1M_RXCLK /M1P_TXCLK	52	I/O	-	M1M_RXCLK Extension MAC2 MII MAC Mode Receive Clock Input. In MII 100Mbps, M1M_RXCLK is 25MHz Clock Input. In MII 10Mbps, M1M_RXCLK is 2.5MHz Clock Input. Used to synchronize M1M_RXD[3:0], M1M_RXDV, and M1P_CRS. M1P_TXCLK Extension MAC2 MII PHY Mode Transmit Clock Output. In MII 100Mbps, M1P_TXCLK is 25MHz Clock Output. In MII 10Mbps, M1P_TXCLK is 2.5MHz Clock Output. Used to synchronize M1P_TXD[3:0] and M1P_TXEN. This pin must be pulled low with a 1K ohm resistor when not used.
M1M_RXDV /M1P_TXEN	53	I	-	M1M_RXDV Extension MAC2 MII MAC Mode Receive Data Valid Input. Receive Data Valid sent synchronously at the rising edge of M1M_RXCLK. M1P_TXEN Extension MAC2 MII PHY Mode Transmit Data Enable Input. Transmit Data Enable is received synchronously at the rising edge of M1P_TXCLK. This pin must be pulled low with a 1K ohm resistor when not used.



Pin Name	Pin No.	Type	Drive (mA)	Description
M1M_RXD0 /M1P_TXD0	54	I	-	M1M_RXD[3:0] Extension MAC2 MII MAC Mode Receive Data Input. Received data that is received synchronously at the rising edge of M1M_RXCLK.
M1M_RXD1 /M1P_TXD1	55			M1P_TXD[3:0] Extension MAC2 MII PHY Mode Transmit Data Input. Transmitted data is received synchronously at the rising edge of M1P_TXCLK.
M1M_RXD2 /M1P_TXD2	56			
M1M_RXD3 /M1P_TXD3	57			These pins must be pulled low with a 1K ohm resistor when not used.

## 7.4. LED Pins

The RTL8367SCI LED pins can be configured to parallel mode LED or serial mode LED interface via register configuration. LED0, LED1, and LED2 of Port n indicate information that can be defined via register or EEPROM.

In parallel mode LED interface, when the LED pin is pulled low, the LED output polarity will be high active. When the LED pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicators, page 36 for more details.

**Table 7. LED Pins**

Pin Name	Pin No.	Type	Drive (mA)	Description
P4LED2 /GP O38 /DIS_SPIS	70	O <sub>PU</sub>	-	Port 4 LED2 Output Signal. P4LED2 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P4LED0 /GP O39 /EEPROM_MOD	71	O <sub>PU</sub>	-	Port 4 LED0 Output Signal. P4LED0 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P4LED1 /GPIO40	72	I/O <sub>PU</sub>	-	Port 4 LED1 Output Signal. P4LED1 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P3LED1 /GPIO41	73	I/O <sub>PU</sub>	-	Port 3 LED1 Output Signal. P3LED1 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P3LED2 /GP O42 /EN_PWRLIGHT	74	O <sub>PU</sub>	-	Port 3 LED2 Output Signal. P3LED2 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P3LED0 /GP O43 /LED_CFG	75	O <sub>PU</sub>	-	Port 3 LED0 Output Signal. P3LED0 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P2LED2 /GP O44 /DIS_8051	76	O <sub>PU</sub>	-	Port 2 LED2 Output Signal. P2LED2 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P2LED0 /GP O45 /DISAUTOLOAD	77	O <sub>PU</sub>	-	Port 2 LED0 Output Signal. P2LED0 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.

Pin Name	Pin No.	Type	Drive (mA)	Description
P2LED1 /GPIO46	78	I/OPU	-	Port 2 LED1 Output Signal. P2LED1 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P1LED2 /GP O47 /RESERVED	79	OPU	-	Port 1 LED2 Output Signal. P1LED2 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P1LED0 /GP O48 /MID29	80	OPU	-	Port 1 LED0 Output Signal. P1LED0 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P1LED1 /GPIO49	81	I/OPU	-	Port 1 LED1 Output Signal. P1LED1 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P0LED2 /GP O50 /EN_PHY	83	OPU	-	Port 0 LED2 Output Signal. P0LED2 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P0LED1 /GPIO51 /LED_DA	84	I/OPU	-	Port 0 LED1 Output Signal. P0LED1 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.
P0LED0 /GP O52 /LED_CK /SMI_SEL	85	OPU	-	Port 0 LED0 Output Signal. P0LED0 indicates information is defined by register or EEPROM. See section 9.18 LED Indicators, page 36 for more details.

## 7.5. Configuration Strapping Pins

**Table 8. Configuration Strapping Pins**

Pin Name	Pin No.	Type	Description
RESERVED	60	AI	Reserved. <i>Note: This pin must be pulled low via an external 1k ohm resistor.</i>
DIS_SPIS /GP O38 /P4LED2	70	OPU	SPI Slave Management Interface Selection. Pull Up: Disable SPI Slave Management Interface Pull Down: Enable SPI Slave Management Interface <i>Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i> <i>When this pin is pulled low, the LED output polarity will be high active. When this pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicators, page 36 for more details.</i>
EEPROM_MOD /GP O39 /P4LED0	71	OPU	EEPROM Mode Selection. Pull Up: EEPROM 24Cxx Size greater than 16K-bit (24C32~24C256) Pull Down: EEPROM 24Cxx Size less than or equal to 16K-bit (24C02~24C16) <i>Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i> <i>When this pin is pulled low, the LED output polarity will be high active. When this pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicators, page 36 for more details.</i>

Pin Name	Pin No.	Type	Description
EN_PWRLIGHT /GP O42 /P3LED2	74	O <sub>PU</sub>	<p>Enable Power on Light.</p> <p>Pull Up: Enable Power on Light</p> <p>Pull Down: Disable Power on Light</p> <p><i>Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i></p> <p><i>When this pin is pulled low, the LED output polarity will be high active. When this pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicators, page 36 for more details.</i></p>
LED_CFG /GP O43 /P3LED0	75	O <sub>PU</sub>	<p>Configure LED Display Mode.</p> <p>Pull Up: LED0 = Spd100(10)/Act; LED1 = Spd1000/Act; LED2 = LED_Off</p> <p>Pull Down: LED0 = Link/Act; LED1 = Spd1000; LED2 = Spd100</p> <p><i>Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i></p> <p><i>When this pin is pulled low, the LED output polarity will be high active. When this pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicators, page 36 for more details.</i></p>
DIS_8051 /GP O44 /P2LED2	76	O <sub>PU</sub>	<p>Disable Embedded 8051.</p> <p>Pull Up: Disable embedded 8051</p> <p>Pull Down: Enable embedded 8051</p> <p><i>Note 1: The strapping pin DISAUTOLOAD and DIS_8051 are for power on or reset initial stage configuration. Refer to Table 9 Configuration Strapping Pins (DISAUTOLOAD and DIS_8051), page 19 for details.</i></p> <p><i>Note 2: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i></p> <p><i>When this pin is pulled low, the LED output polarity will be high active. When this pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicator, page 36 for more details.</i></p>
DISAUTOLOAD /GP O45 /P2LED0	77	O <sub>PU</sub>	<p>Disable EEPROM Autoload.</p> <p>Pull Up: Disable EEPROM autoload</p> <p>Pull Down: Enable EEPROM autoload</p> <p><i>Note 1: The strapping pin DISAUTOLOAD and DIS_8051 are for power on or reset initial stage configuration. Refer to Table 9 Configuration Strapping Pins (DISAUTOLOAD and DIS_8051), page 19 for details.</i></p> <p><i>Note 2: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i></p> <p><i>When this pin is pulled low, the LED output polarity will be high active. When this pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicators, page 36 for more details.</i></p>
RESERVED /GP O47 /P1LED2	79	O <sub>PU</sub>	<p>Internal Use/Reserved.</p> <p><i>Note: This pin must be kept floating, or pulled high via an external 4.7k ohm resistor upon power on or reset.</i></p> <p><i>When pulled high, the LED output polarity will be low active. See section 9.18 LED Indicators, page 36 for more details.</i></p>

Pin Name	Pin No.	Type	Description
MID29 /GP O48 /P1LED0	80	O <sub>PU</sub>	Select MID29. Pull Up: MII Management Interface PHY ID is 29 Pull Down: MII Management Interface PHY ID is 0 <i>Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i> <i>When this pin is pulled low, the LED output polarity will be high active. When this pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicators, page 36 for more details.</i>
EN_PHY /GP O50 /P0LED2	83	O <sub>PU</sub>	Enable Embedded PHY. Pull Up: Enable embedded PHY Pull Down: Disable embedded PHY <i>Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i> <i>When this pin is pulled low, the LED output polarity will be high active. When this pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicators, page 36 for more details.</i>
SMI_SEL /GP O52 /P0LED0 /LED_CK	85	O <sub>PU</sub>	EEPROM SMI/MII Management Interface Selection. Pull Up: EEPROM SMI interface when DIS_SPIS = 1 Pull Down: MII Management interface when DIS_SPIS = 1 <i>Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i> <i>When this pin is pulled low, the LED output polarity will be high active. When this pin is pulled high, the LED output polarity will change from high active to low active. See section 9.18 LED Indicators, page 36 for more details.</i>
EN_EEE /GP O54 /SCK /SPIS_CK /MDC	91	O	Enable IEEE 802.3az Energy Efficient Ethernet (EEE). Pull Up: Enable Energy Efficient Ethernet (EEE) function Pull Down: Disable Energy Efficient Ethernet (EEE) function <i>Note: This pin must be pulled high or low via an external 4.7k ohm resistor upon power on or reset.</i>

### 7.5.1. Configuration Strapping Pins (DISAUTOLOAD and DIS\_8051)

**Table 9. Configuration Strapping Pins (DISAUTOLOAD and DIS\_8051)**

DISAUTOLOAD	DIS_8051	Initial Stage (Power On or Reset) Loading Data	
		From	To
0	0	EEPROM	Embedded 8051 Instruction Memory
	1	EEPROM	Register
1	Irrelevant	Do Nothing	Do Nothing

## 7.6. Management Interface Pins

**Table 10. Management Interface Pins**

Pin Name	Pin No.	Type	Description
INTERRUPT /GPIO13 /M1M_CRS	44	I/O <sub>PD</sub>	Interrupt output when Interrupt even occurs. Active High by pull-down to GND via a 1K resistor. Active Low by pull-up to DVDDIO_1 via a 4.7K resistor.
SPIS_nCS /GPIO53	90	I/O <sub>PU</sub>	When DIS_SPIS is Pulled Low, SPI Slave Management Interface is Enabled. This pin acts as SPI slave mode Chip Selection Input pin. When DIS_SPIS is Pulled Up, SPI Slave Management Interface is Disabled. This pin is unused.
SPIS_CK /GP_O54 /SCK /MDC /EN_EEE	91	O	When DIS_SPIS is Pulled Low, SPI Slave Management Interface is Enabled. This pin acts as SPI slave mode Serial Clock Input pin. When DIS_SPIS is Pulled Up, SPI Slave Management Interface is Disabled. This pin acts as EEPROM SMI Interface Clock/MII Management Interface (MMD) Clock (selected via the hardware strapping pin, SMI_SEL).
SPIS_DI /GPIO55 /SDA /MDIO	92	I/O	When DIS_SPIS is Pulled Low, SPI Slave Management Interface is Enabled. This pin acts as SPI slave mode Serial Data Input pin. When DIS_SPIS is Pulled Up, SPI Slave Management Interface is Disabled. This pin acts as EEPROM SMI Interface Data/MII Management Interface (MMD) Data (selected via the hardware strapping pin, SMI_SEL).
SPIS_DO /GPIO56	93	I/O	When DIS_SPIS is Pulled Low, SPI Slave Management Interface is Enabled. This pin acts as SPI slave mode Serial Data Output pin. When DIS_SPIS is Pulled Up, SPI Slave Management Interface is Disabled. This pin is unused.

## 7.7. Miscellaneous Pins

**Table 11. Miscellaneous Pins**

Pin Name	Pin No.	Type	Description
MDIREF	12	AO	Reference Resistor. A 2.49K ohm (1%) resistor must be connected between MDIREF and GND.
XTALO	87	AO	25MHz Crystal Clock Output Pin. 25MHz +/-50ppm tolerance crystal output.
XTALI	88	AI	25MHz Crystal Clock Input and Feedback Pin. 25MHz +/-50ppm tolerance crystal reference or oscillator input. When using a crystal, connect a loading capacitor from each pad to ground. When either using an oscillator or driving an external 25MHz clock from another device, XTALO should be kept floating. The maximum XTALI input voltage is 3.3V.
nRESET	89	I <sub>PU</sub>	System Reset Input Pin. When low active will reset the RTL8367SCI.
RESERVED	63, 64	AO	Reserved. Must be left floating.
GPIO13 /INTERRUPT /M1M_CRS	44	I/O <sub>PD</sub>	General Purpose Input/Output Interface IO13.

Pin Name	Pin No.	Type	Description
GPIO19 /RG1_TXD3 /M1M_TXD3 /M1P_RXD3	46	I/O	General Purpose Input/Output Interface IO19.
GPIO20 /RG1_TXD2 /M1M_TXD2 /M1P_RXD2	47	I/O	General Purpose Input/Output Interface IO20.
GPIO21 /RG1_TXD1 /M1M_TXD1 /M1P_RXD1	48	I/O	General Purpose Input/Output Interface IO21.
GPIO22 /RG1_TXD0 /M1M_TXD0 /M1P_RXD0	49	I/O	General Purpose Input/Output Interface IO22.
GPIO23 /RG1_TXCTL /M1M_TXEN /M1P_RXDV	50	I/O	General Purpose Input/Output Interface IO23.
GPIO24 /RG1_TXCLK /M1M_TXCLK /M1P_RXCLK	51	I/O	General Purpose Input/Output Interface IO24.
GPIO28 /RG1_RXCLK /M1M_RXCLK /M1P_TXCLK	52	I/O	General Purpose Input/Output Interface IO28.
GPIO29 /RG1_RXCTL /M1M_RXDV /M1P_TXEN	53	I/O	General Purpose Input/Output Interface IO29.
GPIO30 /RG1_RXD0 /M1M_RXD0 /M1P_TXD0	54	I/O	General Purpose Input/Output Interface IO30.
GPIO31 /RG1_RXD1 /M1M_RXD1 /M1P_TXD1	55	I/O	General Purpose Input/Output Interface IO31.
GPIO32 /RG1_RXD2 /M1M_RXD2 /M1P_TXD2	56	I/O	General Purpose Input/Output Interface IO32.
GPIO33 /RG1_RXD3 /M1M_RXD3 /M1P_TXD3	57	I/O	General Purpose Input/Output Interface IO33.

Pin Name	Pin No.	Type	Description
GPIO37	67	I/O <sub>PU</sub>	General Purpose Input/Output Interface IO67.
GP O38 /P4LED2 /DIS_SPIS	70	O <sub>PU</sub>	General Purpose Output Interface O38.
GP O39 /P4LED0 /EEPROM_MOD	71	O <sub>PU</sub>	General Purpose Output Interface O39.
GPIO40 /P4LED1	72	I/O <sub>PU</sub>	General Purpose Input/Output Interface IO40.
GPIO41 /P3LED1	73	I/O <sub>PU</sub>	General Purpose Input/Output Interface IO41.
GP O42 /P3LED2 /EN_PWRLIGHT	74	O <sub>PU</sub>	General Purpose Output Interface O42.
GP O43 /P3LED0 /LED_CFG	75	O <sub>PU</sub>	General Purpose Output Interface O43.
GP O44 /P2LED2 /DIS_8051	76	O <sub>PU</sub>	General Purpose Output Interface O44.
GP O45 /P2LED0 /DISAUTOLOAD	77	O <sub>PU</sub>	General Purpose Output Interface O45.
GPIO46 /P2LED1	78	I/O <sub>PU</sub>	General Purpose Input/Output Interface IO46.
GP O47 /P1LED2 /RESERVED	79	O <sub>PU</sub>	General Purpose Output Interface O47.
GP O48 /P1LED0 /MID29	80	O <sub>PU</sub>	General Purpose Output Interface O48.
GPIO49 /P1LED1	81	I/O <sub>PU</sub>	General Purpose Input/Output Interface IO49.
GP O50 /P0LED2 /EN_PHY	83	O <sub>PU</sub>	General Purpose Output Interface O50.
GPIO51 /P0LED1 /LED_DA	84	I/O <sub>PU</sub>	General Purpose Input/Output Interface IO51.
GP O52 /P0LED0 /LED_CK /SMI_SEL	85	O <sub>PU</sub>	General Purpose Output Interface O52.
GPIO53 /SPIS_nCS	90	I/O <sub>PU</sub>	General Purpose Input/Output Interface IO53.



Pin Name	Pin No.	Type	Description
GP O54 /SCK /SPIS_CK /MDC /EN_EEE	91	O	General Purpose Output Interface O54.
GPIO55 /SDA /SPIS_DI /MDIO	92	I/O	General Purpose Input/Output Interface IO55.
GPIO56 /SPIS_DO	93	I/O	General Purpose Input/Output Interface IO56.
NC	15	-	No connection.

## 7.8. Test Pins

**Table 12. Test Pins**

Pin Name	Pin No.	Type	Description
ATESTCK	116	AO	Reserved for Internal Use. Must be left floating.
RTT1	14	AO	Reserved for Internal Use. Must be left floating.

## 7.9. Power and GND Pins

**Table 13. Power and GND Pins**

Pin Name	Pin No.	Type	Description
DVDDIO	68, 82	P	Digital I/O High Voltage Power for LED, Management Interface and nRESET.
DVDDIO_1	45, 59	P	Digital I/O High Voltage Power for Extension General Purpose Interface and INTERRUPT.
DVDDL	17, 58, 69	P	Digital Low Voltage Power.
AVDDH	10, 16, 18, 28, 86, 94, 104, 114, 118, 128	AP	Analog High Voltage Power.
AVDDL	5, 13, 23, 99, 109, 123	AP	Analog Low Voltage Power.
PLLVDL	115	AP	PLL Low Voltage Power.
SVDDH	29	AP	SerDes High Voltage Power.
SVDDL_1	33	AP	SerDes1 Low Voltage Power.
SVDDL_0	40	AP	SerDes0 Low Voltage Power.
RESERVED	65, 66	AP	Reserved. Must be connected to DVDDIO.
GND	E-pad	G	GND.
AGND	11	AG	Analog GND.
PLLGND	117	AG	PLL GND.
SGND_1	30, 36	AG	SerDes1 GND.
SGND_0	37, 43	AG	SerDes0 GND.
RESERVED	61, 62	AG	Reserved. Must be connected to GND.

## **8. Physical Layer Functional Overview**

### **8.1. MDI Interface**

The RTL8367SCI embeds five 10/100/1000M Ethernet PHYs in one chip. Each port uses a single common MDI interface to support 1000Base-T, 100Base-TX, and 10Base-T. This interface consists of four signal pairs-A, B, C, and D. Each signal pair consists of two bi-directional pins that can transmit and receive at the same time. The MDI interface has internal termination resistors, and therefore reduces BOM cost and PCB complexity. For 1000Base-T, all four pairs are used in both directions at the same time. For 10/100 links and during auto-negotiation, only pairs A and B are used.

### **8.2. 1000Base-T Transmit Function**

The 1000Base-TX transmit function performs 8B/10B coding, scrambling, and 4D-PAM5 encoding. These code groups are passed through a waveform-shaping filter to minimize EMI effects, and are transmitted onto 4-pair CAT5 cable at 125MBaud/s through a D/A converter.

### **8.3. 1000Base-T Receive Function**

Input signals from the media pass through the sophisticated on-chip hybrid circuit to subtract the transmitted signal from the input signal for effective reduction of near-end echo. The received signal is then processed with state-of-the-art technology, e.g., adaptive equalization, BLW (Baseline Wander) correction, cross-talk cancellation, echo cancellation, timing recovery, error correction, and 4D-PAM5 decoding. The 8-bit-wide data is recovered and is sent to the GMII interface at a clock speed of 125MHz. The RX MAC retrieves the packet data from the internal receive MII/GMII interface and sends it to the packet buffer manager.

### **8.4. 100Base-TX Transmit Function**

The 100Base-TX transmit function performs parallel to serial conversion, 4B/5B coding, scrambling, NRZ/NRZI conversion, and MLT-3 encoding. The 5-bit serial data stream after 4B/5B coding is then scrambled as defined by the TP-PMD Stream Cipher function to flatten the power spectrum energy such that EMI effects can be reduced significantly.

The scrambled seed is based on PHY addresses and is unique for each port. After scrambling, the bit stream is driven onto the network media in the form of MLT-3 signaling. The MLT-3 multi-level signaling technology moves the power spectrum energy from high frequency to low frequency, which also reduces EMI emissions.

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### ***8.5. 100Base-TX Receive Function***

The receive path includes a receiver composed of an adaptive equalizer and DC restoration circuits (to compensate for an incoming distorted MLT-3 signal), an MLT-3 to NRZI and NRZI to NRZ converter to convert analog signals to digital bit-stream, and a PLL circuit to clock data bits with minimum bit error rate. A de-scrambler, 5B/4B decoder, and serial-to-parallel conversion circuits are followed by the PLL circuit. Finally, the converted parallel data is fed into the MAC.

### ***8.6. 10Base-T Transmit Function***

The output 10Base-T waveform is Manchester-encoded before it is driven onto the network media. The internal filter shapes the driven signals to reduce EMI emissions, eliminating the need for an external filter.

### ***8.7. 10Base-T Receive Function***

The Manchester decoder converts the incoming serial stream to NRZ data when the squelch circuit detects the signal level is above squelch level.

### ***8.8. Auto-Negotiation for UTP***

The RTL8367SCI obtains the states of duplex, speed, and flow control ability for each port in UTP mode through the auto-negotiation mechanism defined in the IEEE 802.3 specifications. During auto-negotiation, each port advertises its ability to its link partner and compares its ability with advertisements received from its link partner. By default, the RTL8367SCI advertises full capabilities (1000Full, 100Full, 100Half, 10Full, 10Half) together with flow control ability.

## 8.9. Crossover Detection and Auto Correction

The RTL8367SCI automatically determines whether or not it needs to crossover between pairs (see Table 14) so that an external crossover cable is not required. When connecting to another device that does not perform MDI crossover, when necessary, the RTL8367SCI automatically switches its pin pairs to communicate with the remote device. When connecting to another device that does have MDI crossover capability, an algorithm determines which end performs the crossover function.

The crossover detection and auto correction function can be disabled via register configuration. The pin mapping in MDI and MDI Crossover mode is given below.

**Table 14. Media Dependent Interface Pin Mapping**

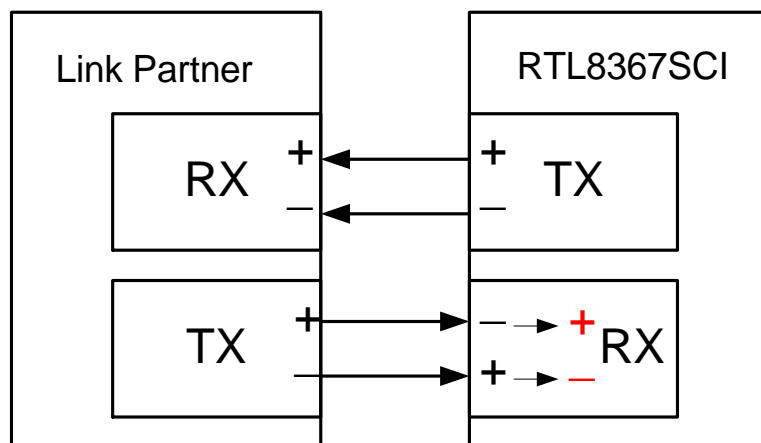
Pairs	MDI			MDI Crossover		
	1000Base-T	100Base-TX	10Base-T	1000Base-T	100Base-TX	10Base-T
A	A	TX	TX	B	RX	RX
B	B	RX	RX	A	TX	TX
C	C	Unused	Unused	D	Unused	Unused
D	D	Unused	Unused	C	Unused	Unused

## 8.10. Polarity Correction

The RTL8367SCI automatically corrects polarity errors on the receiver pairs in 1000Base-T and 10Base-T modes. In 100Base-TX mode, the polarity is irrelevant.

In 1000Base-T mode, receive polarity errors are automatically corrected based on the sequence of idle symbols. Once the de-scrambler is locked, the polarity is also locked on all pairs. The polarity becomes unlocked only when the receiver loses lock.

In 10Base-T mode, polarity errors are corrected based on the detection of valid spaced link pulses. The detection begins during the MDI crossover detection phase and locks when the 10Base-T link is up. The polarity becomes unlocked when the link is down.



**Figure 5. Conceptual Example of Polarity Correction**

## 9. General Function Description

### 9.1. *Reset*

#### 9.1.1. Hardware Reset

In a power-on reset, an internal power-on reset pulse is generated and the RTL8367SCI will start the reset initialization procedures. These are:

- Determine various default settings via the hardware strap pins at the end of the nRESET signal
- Autoload the configuration from EEPROM if EEPROM is detected
- Complete the embedded SRAM BIST process
- Initialize the packet buffer descriptor allocation
- Initialize the internal registers and prepare them to be accessed by the external CPU

#### 9.1.2. Software Reset

The RTL8367SCI supports two software resets; a chip reset and a soft reset.

##### 9.1.2.1 *CHIP\_RESET*

When CHIP\_RESET is set to 0b1 (write and self-clear), the chip will take the following steps:

1. Download configuration from strap pin and EEPROM
2. Start embedded SRAM BIST (Built-In Self Test)
3. Clear all the Lookup and VLAN tables
4. Reset all registers to default values
5. Restart the auto-negotiation process

##### 9.1.2.2 *SOFT\_RESET*

When SOFT\_RESET is set to 0b1 (write and self-clear), the chip will take the following steps:

1. Clear the FIFO and re-start the packet buffer link list
2. Restart the auto-negotiation process

### 9.2. *IEEE 802.3x Full Duplex Flow Control*

The RTL8367SCI supports IEEE 802.3x flow control in 10/100/1000M modes. Flow control can be decided in two ways:

- When Auto-Negotiation is enabled, flow control depends on the result of NWay
- When Auto-Negotiation is disabled, flow control depends on register definition

### ***9.3. Half Duplex Flow Control***

In half duplex mode, the CSMA/CD media access method is the means by which two or more stations share a common transmission medium. To transmit, a station waits (defers) for a quiet period on the medium (that is, no other station is transmitting) and then sends the intended message in bit-serial form. If the message collides with that of another station, then each transmitting station intentionally transmits for an additional predefined period to ensure propagation of the collision throughout the system. The station remains silent for a random amount of time (backoff) before attempting to transmit again.

When a transmission attempt has terminated due to a collision, it is retried until it is successful. The scheduling of the retransmissions is determined by a controlled randomization process called “Truncated Binary Exponential Backoff”. At the end of enforcing a collision (jamming), the switch delays before attempting to retransmit the frame. The delay is an integer multiple of slot time (512-bit times). The number of slot times to delay before the *n*th retransmission attempt is chosen as a uniformly distributed random integer ‘*r*’ in the range:

$$0 \leq r < 2k$$

where:

$k = \min(n, \text{backoffLimit})$ . The backoffLimit for the RTL8367SCI is 9.

The half duplex back-off algorithm in the RTL8367SCI does not have the maximum retry count limitation of 16 (as defined in IEEE 802.3). This means packets in the switch will not be dropped if the back-off retry count is over 16.

#### **9.3.1. Back-Pressure Mode**

In Back-Pressure mode, the RTL8367SCI sends a 4-byte jam pattern (data=0xAA) to collide with incoming packets when congestion control is activated. The Jam pattern collides at the fourth byte counted from the preamble. The RTL8367SCI supports 48PASS1, which receives one packet after 48 consecutive jam collisions (data collisions are not included in the 48). Enable this function to prevent port partition after 63 consecutive collisions (data collisions + consecutive jam collisions).

## ***9.4. Search and Learning***

### **Search**

When a packet is received, the RTL8367SCI uses the destination MAC address and Filtering Identifier (FID) to search the 2K-entry look-up table. The 48-bit MAC address and 2-bit FID use a hash algorithm, to calculate an 9-bit index value. The RTL8367SCI uses the index to compare the packet MAC address with the entries (MAC addresses) in the look-up table. This is the 'Address Search'. If the destination MAC address is not found, the switch will broadcast the packet according to VLAN configuration.

### **Learning**

The RTL8367SCI uses the source MAC address and FID of the incoming packet to hash into a 9-bit index. It then compares the source MAC address with the data (MAC addresses) in this index. If there is a match with one of the entries, the RTL8367SCI will update the entry with new information. If there is no match and the 2K entries are not all occupied by other MAC addresses, the RTL8367SCI will record the source MAC address and ingress port number into an empty entry. This process is called 'Learning'.

Address aging is used to keep the contents of the address table correct in a dynamic network topology. The look-up engine will update the time stamp information of an entry whenever the corresponding source MAC address appears. An entry will be invalid (aged out) if its time stamp information is not refreshed by the address learning process during the aging time period. The aging time of the RTL8367SCI is between 200 and 400 seconds (typical is 300 seconds).

## ***9.5. SVL and IVL/SVL***

The RTL8367SCI supports a 4-group Filtering Identifier (FID) for L2 search and learning. In default operation, all VLAN entries belong to the same FID. This is called Shared VLAN Learning (SVL). If VLAN entries are configured to different FIDs, then the same source MAC address with multiple FIDs can be learned into different look-up table entries. This is called Independent VLAN Learning and Shared VLAN Learning (IVL/SVL).

## ***9.6. Illegal Frame Filtering***

Illegal frames such as CRC error packets, runt packets (length < 64-byte), and oversize packets (length > maximum length) will be discarded by the RTL8367SCI. The maximum packet length may be set from 1518-byte to 16K-byte.



## 9.7. IEEE 802.3 Reserved Group Addresses Filtering Control

The RTL8367SCI supports the ability to drop/forward IEEE 802.3 specified reserved group MAC addresses: 01-80-C2-00-00-00 to 01-80-C2-00-00-2F. The default setting enables forwarding of these reserved group MAC address control frames. Frames with group MAC address 01-80-C2-00-00-01 (802.3x Pause) and 01-80-C2-00-00-02 (802.3ad LACP) will always be filtered. Table 15 shows the Reserved Multicast Address (RMA) configuration mode from 01-80-C2-00-00-00 to 01-80-C2-00-00-2F.

**Table 15. Reserved Multicast Address Configuration Table**

Assignment	Value
Bridge Group Address	01-80-C2-00-00-00
IEEE Std 802.3, 1988 Edition, Full Duplex PAUSE Operation	01-80-C2-00-00-01
IEEE Std 802.3ad Slow Protocols-Multicast Address	01-80-C2-00-00-02
IEEE Std 802.1X PAE Address	01-80-C2-00-00-03
Provider Bridge Group Address	01-80-C2-00-00-08
Undefined 802.1 Address	01-80-C2-00-00-04 ~ 01-80-C2-00-00-07 & 01-80-C2-00-00-09 ~ 01-80-C2-00-00-0C & 01-80-C2-00-00-0F
Provider Bridge MVRP Address	01-80-C2-00-00-0D
IEEE Std 802.1AB Link Layer Discovery Protocol Address	01-80-C2-00-00-0E
All LANs Bridge Management Group Address	01-80-C2-00-00-10
Load Server Generic Address	01-80-C2-00-00-11
Loadable Device Generic Address	01-80-C2-00-00-12
Undefined 802.1 Address	01-80-C2-00-00-13 ~ 01-80-C2-00-00-17 & 01-80-C2-00-00-19 & 01-80-C2-00-00-1B ~ 01-80-C2-00-00-1F
Generic Address for All Manager Stations	01-80-C2-00-00-18
Generic Address for All Agent Stations	01-80-C2-00-00-1a
GMRP Address	01-80-C2-00-00-20
GVRP Address	01-80-C2-00-00-21
Undefined GARP Address	01-80-C2-00-00-22   01-80-C2-00-00-2F
CDP(Cisco Discovery Protocol)	01-00-0C-CC-CC-CC
CSSTP(Cisco Shared Spanning Tree Protocol)	01-00-0C-CC-CC-CD
LLDP	(01:80:c2:00:00:0e or 01:80:c2:00:00:03 or 01:80:c2:00:00:00) && ethertype = 0x88CC

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## ***9.8. Broadcast/Multicast/Unknown DA Storm Control***

The RTL8367SCI enables or disables per-port broadcast/multicast/unknown DA storm control by setting registers (default is disabled). After the receiving rate of broadcast/multicast/unknown DA packets exceeds a reference rate (number of Kbps per second or number of packets per second), all other broadcast/multicast/unknown DA packets will be dropped. The reference rate is set via register configuration.

## ***9.9. Port Security Function***

The RTL8367SCI supports three types of security function to prevent malicious attacks:

- Per-port enable/disable SA auto-learning for an ingress packet
- Per-port enable/disable look-up table aging update function for an ingress packet
- Per-port enable/disable drop all unknown DA packets

## ***9.10. MIB Counters***

The RTL8367SCI supports a set of counters to support management functions.

- MIB-II (RFC 1213)
- Ethernet-Like MIB (RFC 3635)
- Interface Group MIB (RFC 2863)
- RMON (RFC 2819)
- Bridge MIB (RFC 1493)
- Bridge MIB Extension (RFC 2674)

## ***9.11. Port Mirroring***

The RTL8367SCI supports one set of port mirroring functions for all ports. The TX, or RX, or both TX/RX packets from multiple mirrored port can be mirrored to one monitor port.

## **9.12. VLAN Function**

The RTL8367SCI supports 4K VLAN groups. These can be configured as port-based VLANs and IEEE 802.1Q tag-based VLANs. Two ingress-filtering and egress-filtering options provide flexible VLAN configuration:

### **Ingress Filtering**

- The acceptable frame type of the ingress process can be set to ‘Admit All’, ‘Admit only Untagged’ or ‘Admit only Tagged’
- ‘Admit’ or ‘Discard’ frames associated with a VLAN for which that port is not in the member set

### **Egress Filtering**

- ‘Forward’ or ‘Discard’ Leaky VLAN frames between different VLAN domains

The VLAN tag can be inserted or removed at the output port. The RTL8367SCI will insert a Port VID (PVID) for untagged frames, or remove the tag from tagged frames. The RTL8367SCI also supports a special insert VLAN tag function to separate traffic from the WAN and LAN sides in Router and Gateway applications.

In router applications, the router may want to know which input port this packet came from. The RTL8367SCI supports Port VID (PVID) for each port and can insert a PVID in the VLAN tag on egress. Using this function, VID information carried in the VLAN tag will be changed to PVID. The RTL8367SCI also provides an option to admit VLAN tagged packets with a specific PVID only. If this function is enabled, it will drop non-tagged packets and packets with an incorrect PVID.

### **9.12.1. Port-Based VLAN**

This default configuration of the VLAN function can be modified via an attached serial EEPROM or EEPROM SMI Slave interface. The 4K-entry VLAN Table designed into the RTL8367SCI provides full flexibility for users to configure the input ports to associate with different VLAN groups. Each input port can join with more than one VLAN group.

Port-based VLAN mapping is the simplest implicit mapping rule. Each ingress packet is assigned to a VLAN group based on the input port. It is not necessary to parse and inspect frames in real-time to determine their VLAN association. All the packets received on a given input port will be forwarded to this port’s VLAN members.

### **9.12.2. IEEE 802.1Q Tag-Based VLAN**

The RTL8367SCI supports 4K VLAN entries to perform 802.1Q tag-based VLAN mapping. In 802.1Q VLAN mapping, the RTL8367SCI uses a 12-bit explicit identifier in the VLAN tag to associate received packets with a VLAN. The RTL8367SCI compares the explicit identifier in the VLAN tag with the 4K VLAN Table to determine the VLAN association of this packet, and then forwards this packet to the member set of that VLAN. Two VIDs are reserved for special purposes. One of them is all 1’s, which is reserved and currently unused. The other is all 0’s, which indicates a priority tag. A priority-tagged frame should be treated as an untagged frame.

When ‘802.1Q tag aware VLAN’ is enabled, the RTL8367SCI performs 802.1Q tag-based VLAN mapping for tagged frames, but still performs port-based VLAN mapping for untagged frames. If ‘802.1Q tag aware

VLAN' is disabled, the RTL8367SCI performs only port-based VLAN mapping both on non-tagged and tagged frames. The processing flow when '802.1Q tag aware VLAN' is enabled is illustrated below.

Two VLAN ingress filtering functions are supported in registers by the RTL8367SCI. One is the 'VLAN tag admit control, which provides the ability to receive VLAN-tagged frames only. Untagged or priority tagged (VID=0) frames will be dropped. The other is 'VLAN member set ingress filtering', which will drop frames if the ingress port is not in the member set.

### **9.12.3. Port VID**

In a router application, the router may want to know which input port this packet came from. The RTL8367SCI supports Port VID (PVID) for each port to insert a PVID in the VLAN tag for untagged or priority tagged packets on egress. When 802.1Q tag-aware VLAN is enabled, VLAN tag admit control is enabled, and non-PVID Discard is enabled at the same time. When these functions are enabled, the RTL8367SCI will drop non-tagged packets and packets with an incorrect PVID.

## **9.13. QoS Function**

The RTL8367SCI supports 8 priority queues and input bandwidth control. Packet priority selection can depend on Port-based priority, 802.1p/Q Tag-based priority, IPv4/IPv6 DSCP-based priority, and ACL-based priority and SVLAN-based priority. When multiple priorities are enabled in the RTL8367SCI, the packet's priority will be assigned based on the priority selection table.

Each queue has one leaky bucket for Average Packet Rate. Per-queue in each output port can be set as Strict Priority (SP) or Weighted Fair Queue (WFQ) for packet scheduling algorithm.

### **9.13.1. Input Bandwidth Control**

Input bandwidth control limits the input bandwidth. When input traffic is more than the RX Bandwidth parameter, this port will either send out a 'pause ON' frame, or drop the input packet depending on register setup. Per-port input bandwidth control rates can be set from 8Kbps to 2.5Gbps (in 8Kbps steps).

### **9.13.2. Priority Assignment**

Priority assignment specifies the priority of a received packet according to various rules. The RTL8367SCI can recognize the QoS priority information of incoming packets to give a different egress service priority.

The RTL8367SCI identifies the priority of packets based on several types of QoS priority information:

- Port-based priority
- 802.1p/Q-based priority
- IPv4/IPv6 DSCP-based priority
- ACL-based priority
- SVLAN-based priority

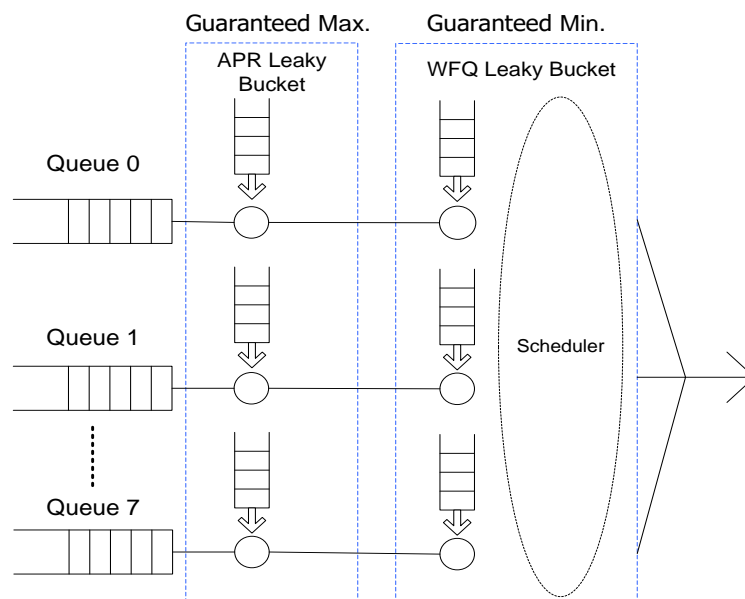
### 9.13.3. Priority Queue Scheduling

The RTL8367SCI supports MAX-MIN packet scheduling.

Packet scheduling offers two modes:

- Average Packet Rate (APR) leaky bucket, which specifies the average rate of one queue
- Weighted Fair Queue (WFQ), which decides which queue is selected in one slot time to guarantee the minimal packet rate of one queue

In addition, each queue of each port can select Strict Priority or WFQ packet scheduling according to packet scheduling mode. Figure 6 shows the RTL8367SCI packet-scheduling diagram.



**Figure 6. RTL8367SCI MAX-MIN Scheduling Diagram**

### 9.13.4. IEEE 802.1p/Q and DSCP Remarking

The RTL8367SCI supports the IEEE 802.1p/Q and IP DSCP (Differentiated Services Code Point) remarking function. When packets egress from one of the 8 queues, the packet's 802.1p/Q priority and IP DSCP can optionally be remarked to a configured value. 802.1p/Q priority & IP DSCP value can be remarked based on internal priority.

### 9.13.5. ACL-Based Priority

The RTL8367SCI supports 64-entry ACL (Access Control List) rules. When a packet is received, its physical port, Layer2, Layer3, and Layer4 information are recorded and compared to ACL entries.

If a received packet matches multiple entries, the entry with the lowest address is valid. If the entry is valid, the action bit and priority bit will be applied.

- If the action bit is 'Drop', the packet will be dropped. If the action bit is 'CPU', the packet will be trapped to the CPU instead of forwarded to non-CPU ports (except where it will be dropped by rules other than the ACL rule)

- If the action bit is 'Permit', ACL rules will override other rules
- If the action bit is 'Mirror', the packet will be forwarded to the mirror port and the L2 lookup result destination port. The mirror port indicates the port configured in the port mirror mechanism
- The priority bit will take effect only if the action bit is 'CPU', 'Permit', and 'Mirror'. The Priority bit is used to determine the packet queue ID according to the priority assignment mechanism

## ***9.14. IEEE 802.1x Function***

The RTL8367SCI supports IEEE 802.1x Port-based Access Control.

- Port-Based Access Control for each port
- Authorized Port-Based Access Control for each port
- Port-Based Access Control Direction for each port

### **9.14.1. Port-Based Access Control**

Each port of the RTL8367SCI can be set to 802.1x port-based authenticated checking function usage and authorized status. Ports with 802.1X unauthorized status will drop received/transmitted frames.

### **9.14.2. Authorized Port-Based Access Control**

If a dedicated port is set to 802.1x port-based access control, and passes the 802.1x authorization, then its port authorization status can be set to authorized.

### **9.14.3. Port-Based Access Control Direction**

Ports with 802.1X unauthorized status will drop received/transmitted frames only when port authorization direction is 'BOTH'. If the authorization direction of an 802.1X unauthorized port is IN, incoming frames to that port will be dropped, but outgoing frames will be transmitted.

## ***9.15. IEEE 802.1D Function***

When using IEEE 802.1D, the RTL8367SCI supports 4 sets and four status' for each port for CPU implementation 802.1D (STP) and 802.1s (MSTP) function:

- Disabled: The port will not transmit/receive packets, and will not perform learning
- Blocking: The port will only receive BPDU spanning tree protocol packets, but will not transmit any packets, and will not perform learning
- Learning: The port will receive any packet, including BPDU spanning tree protocol packets, and will perform learning, but will only transmit BPDU spanning tree protocol packets
- Forwarding: The port will transmit/receive all packets, and will perform learning

The RTL8367SCI also supports a per-port transmission/reception enable/disable function. Users can control the port state via register.

## 9.16. Embedded 8051

An 8051 MCU is embedded in the RTL8367SCI to support management functions. The 8051 MCU can access all of the registers in the RTL8367SCI through the internal bus. The features of the 8051 MCU are listed below:

- 256-byte fast internal RAM
- On-chip 8K-byte data memory
- On-chip 8K-byte code memory
- Supports code-banking
- EEPROM read/write ability

## 9.17. Realtek Cable Test (RTCT)

The RTL8367SCI physical layer transceivers use DSP technology to implement the Realtek Cable Test (RTCT) feature. The RTCT function can be used to detect short, open, or impedance mismatch in each differential pair. The RTL8367SCI also provides LED support to indicate test status and results.

## 9.18. LED Indicators

The RTL8367SCI supports parallel LEDs for each port. Each port has three LED indicator pins, LED0, LED1, and LED2. Each pin may have different indicator information (defined in Table 16). Refer to section 7.4 LED Pins, page 16 for pin details. Upon reset, the RTL8367SCI supports chip diagnostics and LED operation test by blinking all LEDs once.

**Table 16. LED Definitions**

LED Statuses	Description
LED_Off	LED Pin Output Disable.
Dup/Col	Duplex/Collision Indicator. Blinking when collision occurs. Low for full duplex, and high for half duplex mode.
Link/Act	Link, Activity Indicator. Low for link established. Link/Act Blinking when the corresponding port is transmitting or receiving.
Spd1000	1000Mbps Speed Indicator. Low for 1000Mbps.
Spd100	100Mbps Speed Indicator. Low for 100Mbps.
Spd10	10Mbps Speed Indicator. Low for 10Mbps.
Spd1000/Act	1000Mbps Speed/Activity Indicator. Low for 1000Mbps. Blinking when the corresponding port is transmitting or receiving.
Spd100/Act	100Mbps Speed/Activity Indicator. Low for 100Mbps. Blinking when the corresponding port is transmitting or receiving.
Spd10/Act	10Mbps Speed/Activity Indicator. Low for 10Mbps. Blinking when the corresponding port is transmitting or receiving.
Spd100(10)/Act	100/10Mbps Speed/Activity Indicator. Low for 100/10Mbps. Blinking when the corresponding port is transmitting or receiving.
Act	Activity Indicator. Act blinking when the corresponding port is transmitting or receiving.



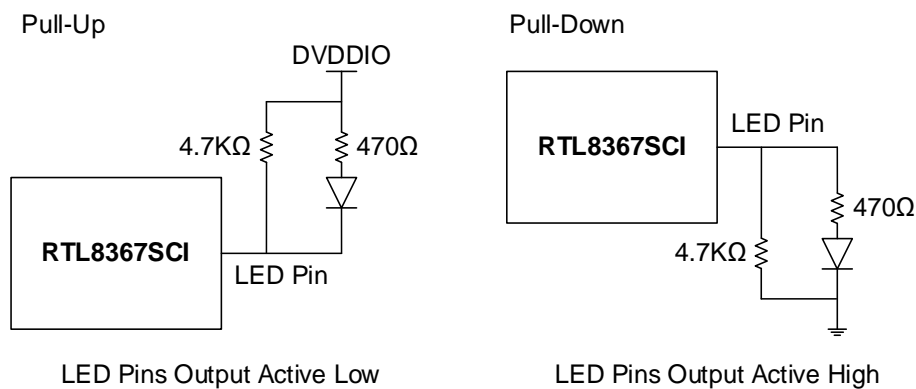
The LED pin also supports pin strapping configuration functions. The PnLED0 and PnLED2 pins are dual-function pins: input operation for configuration upon reset, and output operation for LED after reset. When the pin input is pulled high upon reset, the pin output is active low after reset. When the pin input is pulled down upon reset, the pin output is active high after reset. For details refer to Figure 7, page 37, and Figure 8, page 37. Typical values for pull-up/pull-down resistors are 4.7K $\Omega$ .

The PnLED1 can be combined with PnLED0 or PnLED2 as a Bi-color LED.

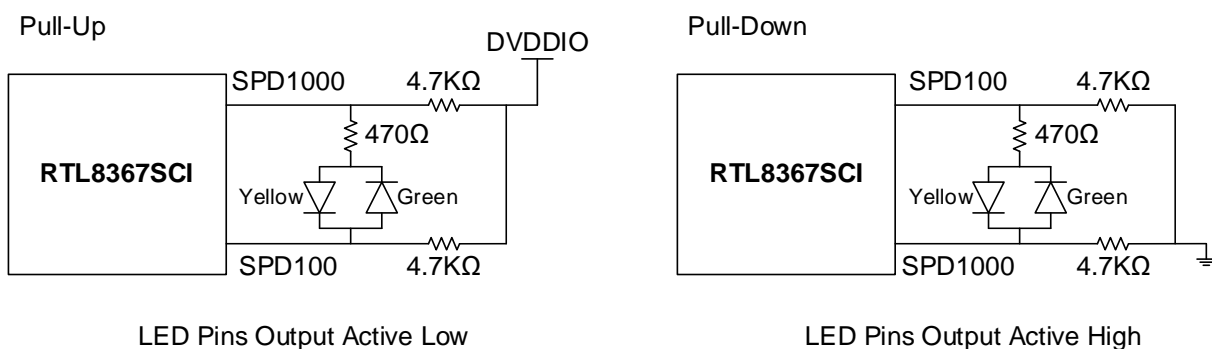
The PnLED1 should operate with the same polarity as other Bi-color LED pins. For example:

- P0LED1 should be pulled up upon reset if P0LED1 is combined with P0LED2 as a Bi-color LED, and P0LED2 input is pulled high upon reset. In this configuration, the output of these pins is active low after reset
- P0LED1 should be pulled down upon reset if P0LED1 is combined with P0LED2 as a Bi-color LED, and P0LED2 input is pulled down upon reset. In this configuration, the output of these pins is active high after reset

Upon reset, the RTL8367SCI supports chip diagnostics and LED functions by blinking all LEDs once. This function can be disabled by asserting EN\_PWRLIGHT to 0b0 (pull down).



**Figure 7. Pull-Up and Pull-Down of LED Pins for Single-Color LED**



**Figure 8. Pull-Up and Pull-Down of LED Pins for Bi-Color LED**



## ***9.19. Green Ethernet***

### **9.19.1. Link-Down Power Saving**

The RTL8367SCI implements link-down power saving on a per-port basis, greatly cutting power consumption when the network cable is disconnected. After it detects an incoming signal, it wakes up from link-down power saving and operates in normal mode.

## ***9.20. IEEE 802.3az Energy Efficient Ethernet (EEE) Function***

The RTL8367SCI supports IEEE 802.3az Energy Efficient Ethernet ability for 1000Base-T and 100Base-TX in full duplex operation.

The Energy Efficient Ethernet (EEE) optional operational mode combines the IEEE 802.3 Media Access Control (MAC) sub-layer with 100Base-TX and 1000Base-T Physical Layers defined to support operation in Low Power Idle mode. When Low Power Idle mode is enabled, systems on both sides of the link can disable portions of the functionality and save power during periods of low link utilization.

- 1000Base-T PHY: Supports Energy Efficient Ethernet with the optional function of Low Power Idle
- 100Base-TX PHY: Supports Energy Efficient Ethernet with the optional function of Low Power Idle

The RTL8367SCI MAC uses Low Power Idle signaling to indicate to the PHY, and to the link partner, that a break in the data stream is expected, and components may use this information to enter power saving modes that require additional time to resume normal operation. Similarly, it informs the LPI Client that the link partner has sent such an indication.

## ***9.21. Interrupt Pin for External CPU***

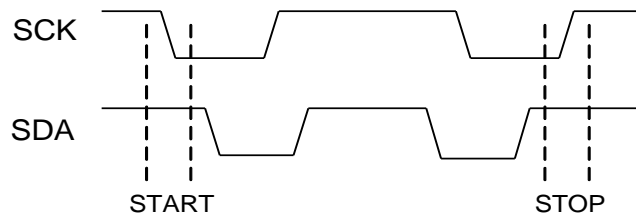
The RTL8367SCI provides one Interrupt output pin to interrupt an external CPU. The polarity of the Interrupt output pin can be configured via register access. In configuration registers, each port has link-up and link-down interrupt flags with mask.

When port link-up or link-down interrupt mask is enabled, the RTL8367SCI will raise the interrupt signal to alarm the external CPU. The CPU can read the interrupt flag to determine which port has changed to which status.

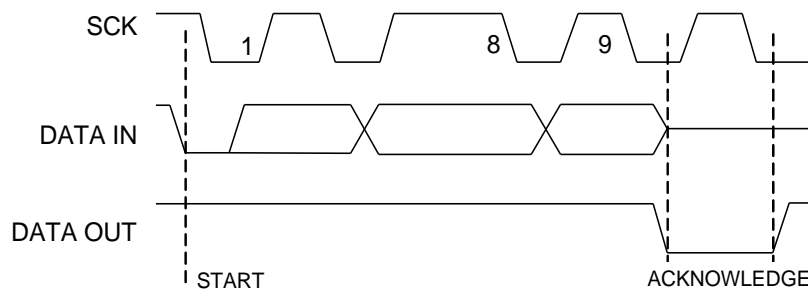
## 10. Interface Descriptions

### 10.1. EEPROM SMI Host to EEPROM

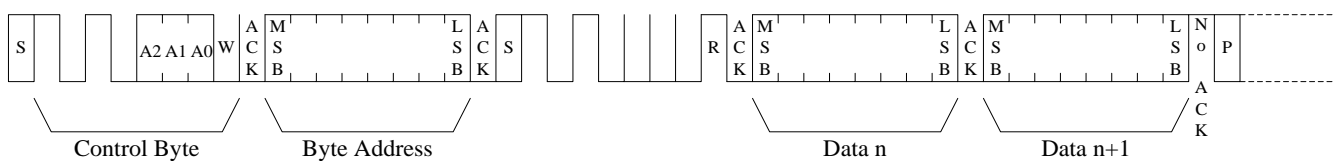
The EEPROM interface of the RTL8367SCI uses the serial bus EEPROM Serial Management Interface (SMI) to read the EEPROM space up to 256K-bit. When the RTL8367SCI is powered up, it drives SCK and SDA to read the registers from the EEPROM.



**Figure 9. SMI Start and Stop Command**



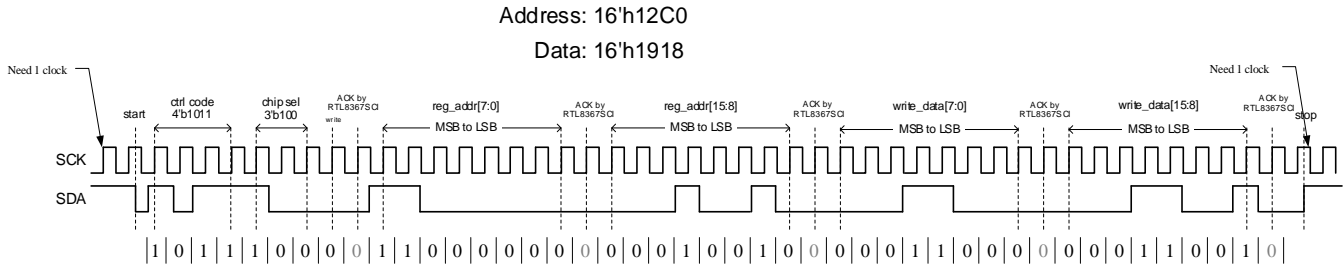
**Figure 10. EEPROM SMI Host to EEPROM**



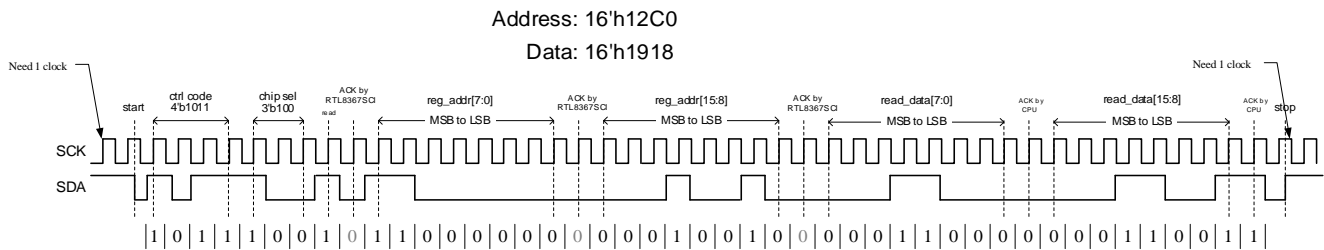
**Figure 11. EEPROM SMI Host Mode Frame**

## 10.2. EEPROM SMI Slave for External CPU

When EEPROM auto-load is complete, the RTL8367SCI registers can be accessed via SCK and SDA by an external CPU. The device address of the RTL8367SCI is 0x4. For the start and end of a write/read command, SCK needs one extra clock before/after the start/stop signals.



**Figure 12. EEPROM SMI Write Command for Slave Mode**



**Figure 13. EEPROM SMI Read Command for Slave Mode**

### 10.3. SPI Slave for External CPU

The RTL8367SCI supports a SPI-Slave Management Interface that can be enabled via Pin configuration (see Table 8, page 17). An External CPU can configure or manage the RTL8367SCI internal register through the SPI interface.

When the CPU writes data to the RTL8367SCI internal register via the SPI interface, the first 8-bit is OP code, and the write command OP code is 8h'02. The second 8-bit define the address [15:8], the third 8-bit are the Address [7:0], the fourth 8-bit are write data [15:8], and the fifth 8-bit are write data [7:0] (see Figure 14).

When the CPU reads data from the RTL8367SCI internal register via the SPI interface, the first 8-bit OP code is 8h'03. The second 8-bit define the address [15:8] and the third 8-bit are the Address [7:0]. The RTL8367SCI returns read data [15:8] at the fourth 8-bit, and data [7:0] at the fifth 8-bit (see Figure 15).

#### 10.3.1. SPI-Slave Interface Access Format

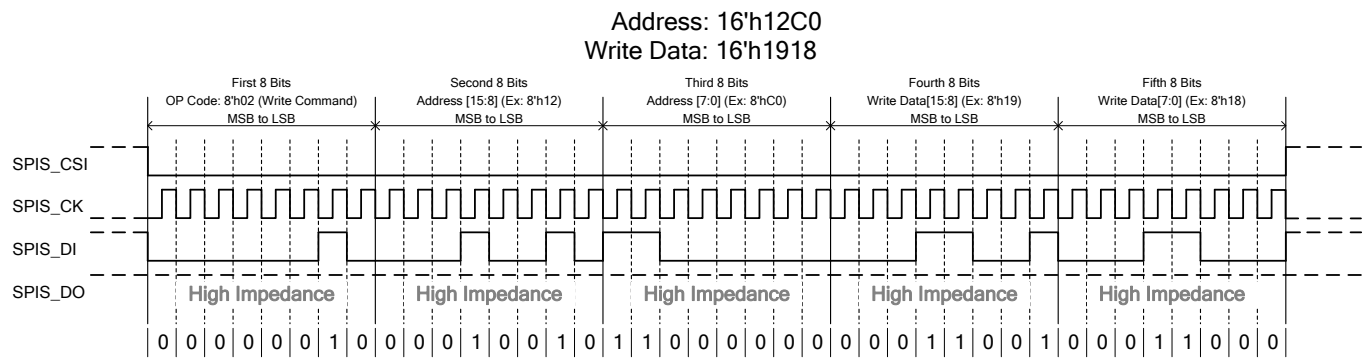


Figure 14. SPI-Slave Write Command Access Format

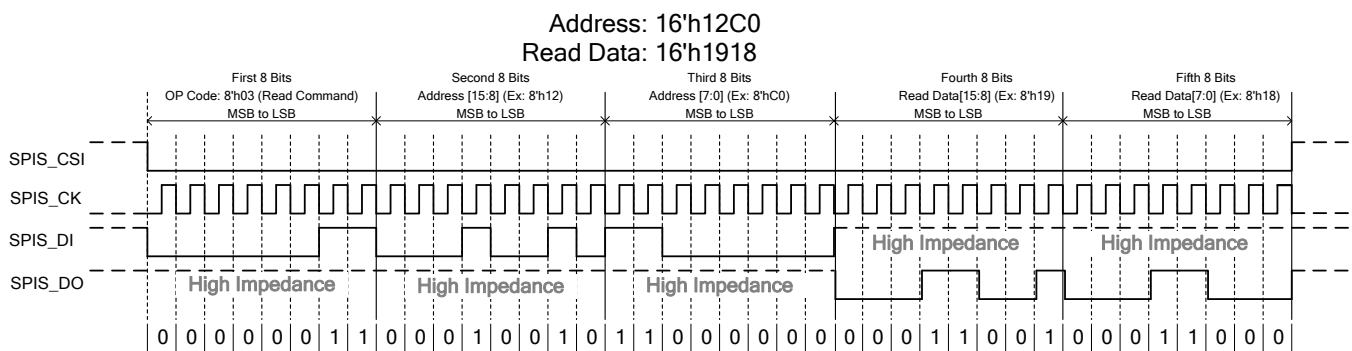


Figure 15. SPI-Slave Read Command Access Format

## 10.4. General Purpose Interface

The RTL8367SCI supports one extension general purpose interface. The interface function mux is summarized in Table 17. The Extension MAC2 of the RTL8367SCI supports RGMII, MII MAC mode or MII PHY mode via register configuration.

**Table 17. RTL8367SCI Extension General Purpose Interface Pin Definitions**

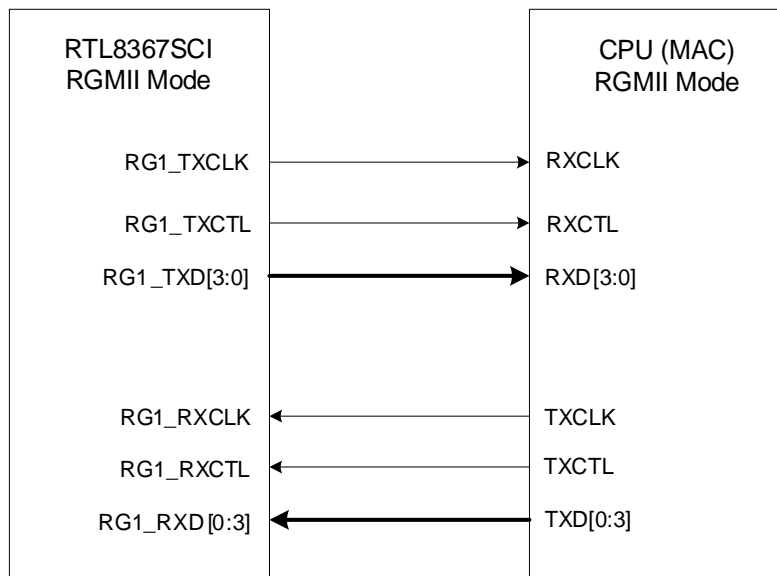
Pin No.	Extension Interface	Type	RGMII	MII MAC Mode	MII PHY Mode
46	E1_DO3	O	RG1_TXD3	M1M_TXD3	M1P_RXD3
47	E1_DO2	O	RG1_TXD2	M1M_TXD2	M1P_RXD2
48	E1_DO1	O	RG1_TXD1	M1M_TXD1	M1P_RXD1
49	E1_DO0	O	RG1_TXD0	M1M_TXD0	M1P_RXD0
50	E1_DOEN	O	RG1_TXCTL	M1M_TXEN	M1P_RXDV
51	E1_DOCLK	O	RG1_TXCLK	M1M_TXCLK	M1P_RXCLK
52	E1_DICLK	I	RG1_RXCLK	M1M_RXCLK	M1P_TXCLK
53	E1_DIDV	I	RG1_RXCTL	M1M_RXDV	M1P_TXEN
54	E1_DI0	I	RG1_RXD0	M1M_RXD0	M1P_TXD0
55	E1_DI1	I	RG1_RXD1	M1M_RXD1	M1P_TXD1
56	E1_DI2	I	RG1_RXD2	M1M_RXD2	M1P_TXD2
57	E1_DI3	I	RG1_RXD3	M1M_RXD3	M1P_TXD3

### 10.4.1. Extension Port RGMII Mode (1Gbps)

The Extension MAC2 of the RTL8367SCI supports one RGMII interface to an external CPU. The pin numbers and names are shown in Table 18. Figure 16 shows the signal diagram for the RGMII mode interface.

**Table 18. Extension MAC2 RGMII Pins**

RTL8367SCI Pin No.	Type	Extension MAC2 RGMII Mode
46, 47, 48, 49	O	RG1_TXD[3:0]
50	O	RG1_TXCTL
51	O	RG1_TXCLK
52	I	RG1_RXCLK
53	I	RG1_RXCTL
54, 55, 56, 57	I	RG1_RXD[0:3]



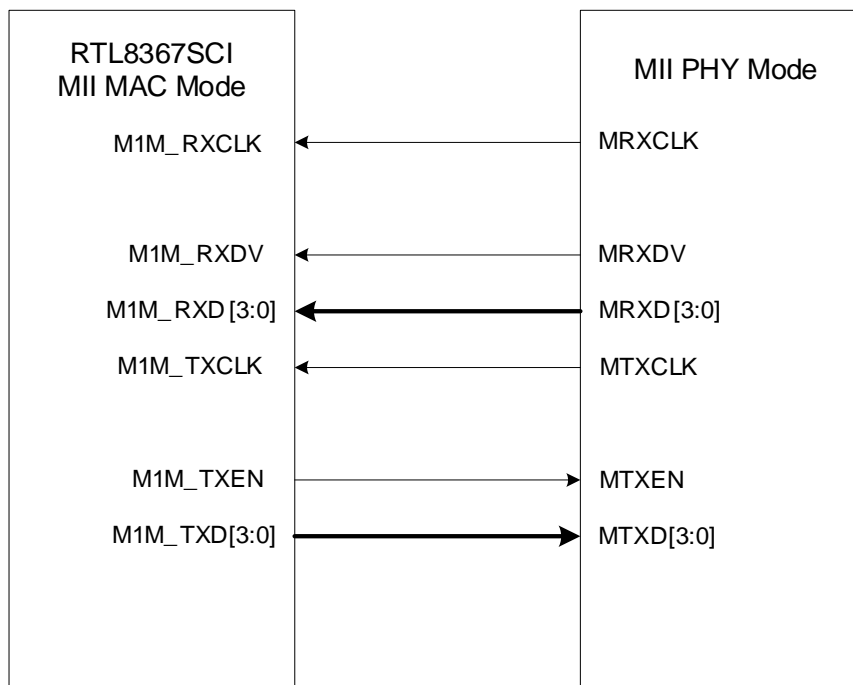
**Figure 16. RGMII Mode Interface Signal Diagram**

### 10.4.2. Extension Port MII MAC/PHY Mode Interface (10/100Mbps)

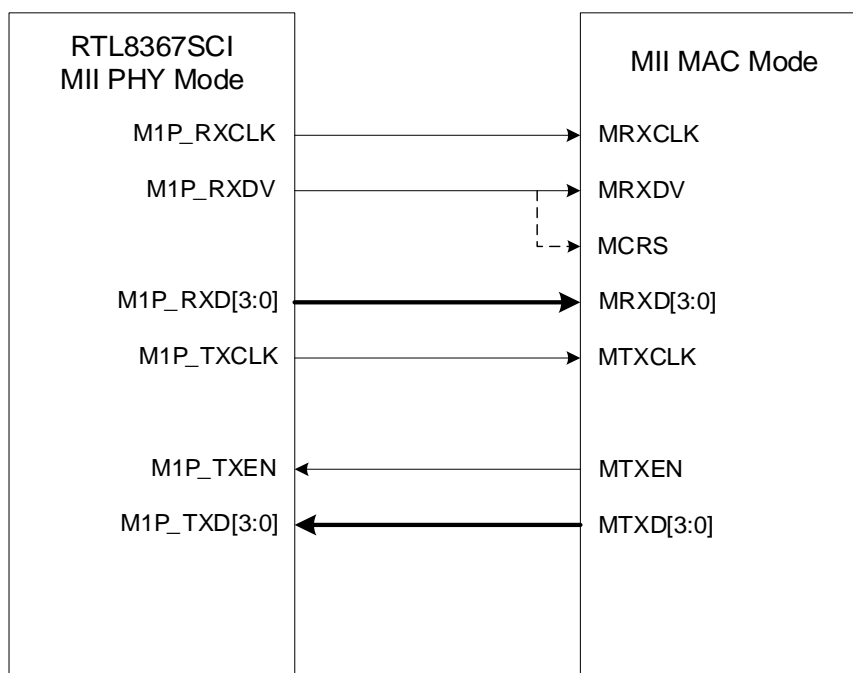
The Extension MAC2 of the RTL8367SCI supports one MII MAC/PHY mode interface to an external CPU. The pin numbers and names are shown in Table 19. Figure 17 shows the signal diagram for the MII MAC mode interface and Figure 18 shows the signal diagram for the MII PHY mode interface.

**Table 19. Extension MAC2 MII Pins**

RTL8367SCI Pin No.	Type	Extension MAC2 MII MAC Mode	Type	Extension MAC2 MII PHY Mode
46, 47, 48, 49	O	M1M_TXD[3:0]	O	M1P_RXD[3:0]
50	O	M1M_TXEN	O	M1P_RXDV
51	I	M1M_TXCLK	O	M1P_RXCLK
52	I	M1M_RXCLK	O	M1P_TXCLK
53	I	M1M_RXDV	I	M1P_TXEN
54, 55, 56, 57	I	M1M_RXD[0:3]	I	M1P_TXD[0:3]



**Figure 17. Signal Diagram of MII MAC Mode Interface (100Mbps)**



**Figure 18. Signal Diagram of MII PHY Mode Interface (100Mbps)**



## 11. Register Descriptions

In this section the following abbreviations are used:

RO: Read Only

LH: Latch High until clear

RW: Read/Write

SC: Self Clearing

LL: Latch Low until clear

### 11.1. PCS Register (PHY 0~4)

**Table 20. PCS Register (PHY 0~4)**

Register	Register Description	Default
0	Control Register	0x1140
1	Status Register	0x7949
2	PHY Identifier 1	0x001C
3	PHY Identifier 2	0xC943
4	Auto-Negotiation Advertisement Register	0x0DE1
5	Auto-Negotiation Link Partner Ability Register	0x0000
6	Auto-Negotiation Expansion Register	0x0004
7	Auto-Negotiation Page Transmit Register	0x2001
8	Auto-Negotiation Link Partner Next Page Register	0x0000
9	1000Base-T Control Register	0x0E00
10	1000Base-T Status Register	0x0000
11~14	Reserved	0x0000
15	Extended Status	0x2000
16~31	ASIC Control Register	-

## 11.2. Register 0: Control

**Table 21. Register 0: Control**

Reg.bit	Name	Mode	Description	Default
0.15	Reset	RW/SC	1: PHY reset 0: Normal operation This bit is self-clearing.	0
0.14	Loopback (Digital Loopback)	RW	1: Enable loopback. This will loopback TXD to RXD and ignore all activity on the cable media 0: Normal operation This function is usable only when this PHY is operated in 10Base-T full duplex, 100Base-TX full duplex, or 1000Base-T full duplex.	0
0.13	Speed Selection[0]	RW	[0.6, 0.13] Speed Selection[1:0] 11: Reserved 10: 1000Mbps 01: 100Mbps 00: 10Mbps This bit can be set through SMI (Read/Write).	0
0.12	Auto Negotiation Enable	RW	1: Enable auto-negotiation process 0: Disable auto-negotiation process This bit can be set through SMI (Read/Write).	1
0.11	Power Down	RW	1: Power down. All functions will be disabled except SMI function 0: Normal operation	0
0.10	Isolate	RW	1: Electrically isolates the PHY from GMII. The PHY is still able to respond to SMI 0: Normal operation	0
0.9	Restart Auto Negotiation	RW/SC	1: Restart Auto-Negotiation process 0: Normal operation	0
0.8	Duplex Mode	RW	1: Full duplex operation 0: Half duplex operation This bit can be set through SMI (Read/Write).	1
0.7	Collision Test	RO	1: Collision test enabled 0: Normal operation When set, this bit will cause the COL signal to be asserted in response to the assertion of TXEN within 512-bit times. The COL signal will be de-asserted within 4-bit times in response to the de-assertion of TXEN.	0
0.6	Speed Selection[1]	RW	See bit 13.	1
0.[5:0]	Reserved	RO	Reserved.	000000

## 11.3. Register 1: Status

**Table 22. Register 1: Status**

Reg.bit	Name	Mode	Description	Default
1.15	100Base-T4	RO	0: No 100Base-T4 capability The RTL8367SCI does not support 100Base-T4 mode and this bit should always be 0.	0
1.14	100Base-TX-FD	RO	1: 100Base-TX full duplex capable 0: Not 100Base-TX full duplex capable	1
1.13	100Base-TX-HD	RO	1: 100Base-TX half duplex capable 0: Not 100Base-TX half duplex capable	1
1.12	10Base-T-FD	RO	1: 10Base-T full duplex capable 0: Not 10Base-T full duplex capable	1
1.11	10Base-T-HD	RO	1: 10Base-T half duplex capable 0: Not 10Base-T half duplex capable	1
1.10	100Base-T2-FD	RO	0: Not 100Base-T2 full duplex capable The RTL8367SCI does not support 100Base-T2 mode and this bit should always be 0.	0
1.9	100Base-T2-HD	RO	0: Not 100Base-T2 half duplex capable The RTL8367SCI does not support 100Base-T2 mode and this bit should always be 0.	0
1.8	Extended Status	RO	1: Extended status information in Register 15 The RTL8367SCI always supports Extended Status Register.	1
1.7	Reserved	RO	Reserved.	0
1.6	MF Preamble Suppression	RO	The RTL8367SCI will accept management frames with preamble suppressed.	1
1.5	Auto-negotiate Complete	RO	1: Auto-negotiation process completed 0: Auto-negotiation process not completed	0
1.4	Remote Fault	RO/LH	1: Remote fault condition detected 0: No remote fault detected This bit will remain set until it is cleared by reading register 1 via the management interface.	0
1.3	Auto-Negotiation Ability	RO	1: Auto-negotiation capable (permanently =1)	1
1.2	Link Status	RO/LL	1: Link is established. If the link fails, this bit will be 0 until after reading this bit again 0: Link has failed since previous read If the link fails, this bit will be set to 0 until bit is read.	0
1.1	Jabber Detect	RO/LH	1: Jabber detected 0: No Jabber detected Jabber is supported only in 10Base-T mode.	0
1.0	Extended Capability	RO	1: Extended register capable (permanently =1)	1

## 11.4. Register 2: PHY Identifier 1

The PHY Identifier Registers #1 and #2 together form a unique identifier for the PHY section of this device. The Identifier consists of a concatenation of the Organizationally Unique Identifier (OUI), the vendor's model number, and the model revision number. A PHY may return a value of zero in each of the 32-bit of the PHY Identifier if desired. The PHY Identifier is intended to support network management.

**Table 23. Register 2: PHY Identifier 1**

Reg.bit	Name	Mode	Description	Default
2.[15:0]	OUI	RO	Composed of the 3 <sup>rd</sup> to 18 <sup>th</sup> bits of the Organizationally Unique Identifier (OUI), respectively.	0x001C

## 11.5. Register 3: PHY Identifier 2

**Table 24. Register 3: PHY Identifier 2**

Reg.bit	Name	Mode	Description	Default
3.[15:10]	OUI	RO	Assigned to the 19 <sup>th</sup> through 24 <sup>th</sup> bits of the OUI.	110010
3.[9:4]	Model Number	RO	Manufacturer's model number.	010100
3.[3:0]	Revision Number	RO	Manufacturer's revision number.	0011

## 11.6. Register 4: Auto-Negotiation Advertisement

This register contains the advertisement abilities of this device as they will be transmitted to its Link Partner during Auto-negotiation.

*Note: Each time the link ability of the RTL8367SCI is reconfigured, the auto-negotiation process should be executed to allow the configuration to take effect.*

**Table 25. Register 4: Auto-Negotiation Advertisement**

Reg.bit	Name	Mode	Description	Default
4.15	Next Page	RO	1: Additional next pages exchange desired 0: No additional next pages exchange desired	0
4.14	Acknowledge	RO	Permanently =0.	0
4.13	Remote Fault	RW	1: Advertises that the RTL8367SCI has detected a remote fault 0: No remote fault detected	0
4.12	Reserved	RO	Reserved.	0
4.11	Reserved	RW	Reserved.	0
4.10	Pause	RW	1: Advertises that the RTL8367SCI has flow control capability 0: No flow control capability	1
4.9	100Base-T4	RO	1: 100Base-T4 capable 0: Not 100Base-T4 capable (Permanently =0)	0
4.8	100Base-TX-FD	RW	1: 100Base-TX full duplex capable 0: Not 100Base-TX full duplex capable	1
4.7	100Base-TX	RW	1: 100Base-TX half duplex capable 0: Not 100Base-TX half duplex capable	1

Reg.bit	Name	Mode	Description	Default
4.6	10Base-T-FD	RW	1: 10Base-T full duplex capable 0: Not 10Base-T full duplex capable	1
4.5	10Base-T	RW	1: 10Base-T half duplex capable 0: Not 10Base-T half duplex capable	1
4.[4:0]	Selector Field	RO	[00001]=IEEE 802.3	00001

Note 1: The setting of Register 4 has no effect unless auto-negotiation is restarted or the link goes down.

Note 2: If 1000Base-T is advertised, then the required next pages are automatically transmitted.

## 11.7. Register 5: Auto-Negotiation Link Partner Ability

This register contains the advertised abilities of the Link Partner as received during Auto-negotiation. The content changes after a successful Auto-negotiation.

**Table 26. Register 5: Auto-Negotiation Link Partner Ability**

Reg.bit	Name	Mode	Description	Default
5.15	Next Page	RO	1: Link partner desires Next Page transfer 0: Link partner does not desire Next Page transfer	0
5.14	Acknowledge	RO	1: Link Partner acknowledges reception of Fast Link Pulse (FLP) words 0: Not acknowledged by Link Partner	0
5.13	Remote Fault	RO	1: Remote Fault indicated by Link Partner 0: No remote fault indicated by Link Partner	0
5.12	Reserved	RO	Reserved.	0
5.11	Asymmetric Pause	RO	1: Asymmetric Flow control supported by Link Partner 0: No Asymmetric flow control supported by Link Partner When auto-negotiation is enabled, this bit reflects Link Partner ability	0
5.10	Pause	RO	1: Flow control supported by Link Partner. 0: No flow control supported by Link Partner When auto-negotiation is enabled, this bit reflects Link Partner ability	0
5.9	100Base-T4	RO	1: 100Base-T4 supported by Link Partner 0: 100Base-T4 not supported by Link Partner	0
5.8	100Base-TX-FD	RO	1: 100Base-TX full duplex supported by Link Partner 0: 100Base-TX full duplex not supported by Link Partner	0
5.7	100Base-TX	RO	1: 100Base-TX half duplex supported by Link Partner 0: 100Base-TX half duplex not supported by Link Partner	0
5.6	10Base-T-FD	RO	1: 10Base-T full duplex supported by Link Partner 0: 10Base-T full duplex not supported by Link Partner	0
5.5	10Base-T	RO	1: 10Base-T half duplex supported by Link Partner 0: 10Base-T half duplex not supported by Link Partner	0
5.[4:0]	Selector Field	RO	[00001]=IEEE 802.3	00000

## 11.8. Register 6: Auto-Negotiation Expansion

**Table 27. Register 6: Auto-Negotiation Expansion**

Reg.bit	Name	Mode	Description	Default
6.[15:5]	Reserved	RO	Ignore on read.	0
6.4	Parallel Detection Fault	RO/ LH	1: A fault has been detected via the Parallel Detection function 0: No fault has been detected via the Parallel Detection function	0
6.3	Link Partner Next Page Ability	RO	1: Link Partner is Next Page able 0: Link Partner is not Next Page able	0
6.2	Local Next Page Ability	RO	Not supported. Permanently =0.	1
6.1	Page Received	RO/ LH	1: A New Page has been received 0: A New Page has not been received	0
6.0	Link Partner Auto-Negotiation Ability	RO	If Auto-Negotiation is enabled, this bit means: 1: Link Partner is Auto-Negotiation able 0: Link Partner is not Auto-Negotiation able	0

## 11.9. Register 7: Auto-Negotiation Page Transmit Register

**Table 28. Register 7: Auto-Negotiation Page Transmit Register**

Reg.bit	Name	Mode	Description	Default
7.15	Next Page	RW	1: Link partner desires Next Page transfer 0: Link partner does not desire Next Page transfer	0
7.14	Reserved	RO	1: A fault has been detected via the Parallel Detection function 0: No fault has been detected via the Parallel Detection function	0
7.13	Message Page	RW	1: Message page 0: No Message page ability	1
7.12	Acknowledge 2	RW	1: Local device has the ability to comply with the message received 0: Local device has no ability to comply with the message received	0
7.11	Toggle	RO	Toggle bit.	0
7.[10:0]	Message/ Unformatted Field	RW	Content of message/unformatted page.	1

## 11.10. Register 8: Auto-Negotiation Link Partner Next Page Register

**Table 29. Register 8: Auto-Negotiation Link Partner Next Page Register**

Reg.bit	Name	Mode	Description	Default
8.15	Next Page	RO	Received Link Code Word Bit 15.	0
8.14	Acknowledge	RO	Received Link Code Word Bit 14.	0
8.13	Message Page	RO	Received Link Code Word Bit 13.	0
8.12	Acknowledge 2	RO	Received Link Code Word Bit 12.	0
8.11	Toggle	RO	Received Link Code Word Bit 11.	0
8.[10:0]	Message/Unformatted Field	RO	Received Link Code Word Bit 10:0.	0

## 11.11. Register 9: 1000Base-T Control Register

**Table 30. Register 9: 1000Base-T Control Register**

Reg.bit	Name	Mode	Description	Default
9.[15:13]	Test Mode	RW	Test Mode Select. 000: Normal mode 001: Test mode 1 – Transmit waveform test 010: Test mode 2 – Transmit jitter test in MASTER mode 011: Test mode 3 – Transmit jitter test in SLAVE mode 100: Test mode 4 – Transmitter distortion test 101, 110, 111: Reserved	000
9.12	MASTER/SLAVE Manual Configuration Enable	RW	1: Enable MASTER/SLAVE manual configuration 0: Disable MASTER/SLAVE manual configuration	0
9.11	MASTER/SLAVE Configuration Value	RW	1: Configure PHY as MASTER during MASTER/SLAVE negotiation, only when bit 9.12 is set to logical one 0: Configure PHY as SLAVE during MASTER/SLAVE negotiation, only when bit 9.12 is set to logical one	1
9.10	Port Type	RW	1: Multi-port device 0: Single-port device	1
9.9	1000Base-T Full Duplex	RW	1: Advertise PHY is 1000Base-T full duplex capable 0: Advertise PHY is not 1000Base-T full duplex capable	1
9.8	1000Base-T Half Duplex	RW	1: Advertise PHY is 1000Base-T half duplex capable 0: Advertise PHY is not 1000Base-T half duplex capable	0
9.[7:0]	Reserved	RW	Reserved.	0

## 11.12. Register 10: 1000Base-T Status Register

**Table 31. Register 10: 1000Base-T Status Register**

Reg.bit	Name	Mode	Description	Default
10.15	MASTER/SLAVE Configuration Fault	RO/LH/SC	1: MASTER/SLAVE configuration fault detected 0: No MASTER/SLAVE configuration fault detected	0
10.14	MASTER/SLAVE Configuration Resolution	RO	1: Local PHY configuration resolved to MASTER 0: Local PHY configuration resolved to SLAVE	0
10.13	Local Receiver Status	RO	1: Local receiver OK 0: Local receiver not OK	0
10.12	Remote Receiver Status	RO	1: Remote receiver OK 0: Remote receiver not OK	0
10.11	Link Partner 1000Base-T Full Duplex	RO	1: Link partner is capable of 1000Base-T full duplex 0: Link partner is not capable of 1000Base-T full duplex	0
10.10	1000Base-T Half Duplex	RO	1: Link partner is capable of 1000Base-T half duplex 0: Link partner is not capable of 1000Base-T half duplex	0
10.[9:8]	Reserved	RO	Reserved.	0
10.[7:0]	Idle Error Count	RO/SC	Idle Error Counter. The counter stops automatically when it reaches 0xFF.	0

## 11.13. Register 15: Extended Status

**Table 32. Register 15: Extended Status**

Reg.bit	Name	Mode	Description	Default
15.15	1000Base-X Full Duplex	RO	1: 1000Base-X full duplex capable 0: Not 1000Base-X full duplex capable	0
15.14	1000Base-X Half Duplex	RO	1: 1000Base-X half duplex capable 0: Not 1000Base-X half duplex capable	0
15.13	1000Base-T Full Duplex	RO	1: 1000Base-T full duplex capable 0: Not 1000Base-T full duplex capable	1
15.12	1000Base-T Half Duplex	RO	1: 1000Base-T half duplex capable 0: Not 1000Base-T half duplex capable	0
15.[11:0]	Reserved	RO	Reserved.	0



## 12. Electrical Characteristics

### 12.1. Absolute Maximum Ratings

WARNING: Absolute maximum ratings are limits beyond which permanent damage may be caused to the device, or device reliability will be affected. All voltages are specified reference to GND unless otherwise specified.

**Table 33. Absolute Maximum Ratings**

Parameter	Min	Max	Units
Junction Temperature (Tj)	-	+125	°C
Storage Temperature	-45	+125	°C
DVDDIO, DVDDIO_1, AVDDH, SVDDH Supply Referenced to GND, AGND, SGND_0 and SGND_1	GND-0.3	+3.63	V
DVDDL, AVDDL, PLLVDDL, SVDDL_0, SVDDL_1 Supply Referenced to GND, AGND, PLLGND, SGND_0 and SGND_1	GND-0.3	+1.155	V
Digital Input Voltage	GND-0.3	VDDIO+0.3	V

### 12.2. Recommended Operating Range

**Table 34. Recommended Operating Range**

Parameter		Min	Typ.	Max	Units
Ambient Operating Temperature (Ta). Industrial Grade.		-40	-	85	°C
DVDDIO, AVDDH and SVDDH Supply Voltage Range		3.135	3.3	3.465	V
DVDDIO_1 Supply Voltage Range	3.3V	3.135	3.3	3.465	V
	2.5V	2.375	2.5	2.625	V
	1.8V	1.710	1.8	1.890	V
DVDDL, AVDDL, PLLVDDL, SVDDL_0 and SVDDL_1 Supply Voltage Range		0.9975	1.05	1.1025	V

## 12.3. Thermal Characteristics

### 12.3.1. Assembly Description

**Table 35. Assembly Description**

<b>Package</b>	Type	E-pad LQFP 128-pin
	Dimension (L×W)	14×14 mm <sup>2</sup>
	Thickness	1.4 mm
<b>PCB</b>	PCB Dimension (L×W)	76.2×114.3 mm <sup>2</sup>
	PCB Thickness	1.6 mm
	Number of Cu Layer-PCB	2-Layer - Top layer (1oz): 20% coverage of Cu - Bottom layer (1oz): 90% coverage of Cu 4-Layer - 1 <sup>st</sup> layer (1oz): 20% coverage of Cu - 2 <sup>nd</sup> layer (1oz): 90% coverage of Cu - 3 <sup>rd</sup> layer (1oz): 90% coverage of Cu - 4 <sup>th</sup> layer (1oz): 20% coverage of Cu

### 12.3.2. Material Properties

**Table 36. Material Properties**

Item		Material	Thermal Conductivity K (W/m-k)
<b>Package</b>	Die	Si	149 at 25°C 107 at 125°C
	Epoxy	EN-4900G	2.0
	Lead Frame	C194	259
	Mold Compound	EME-G631H	0.9
<b>PCB</b>		Cu	389
		FR-4	0.3

### 12.3.3. Simulation Conditions

**Table 37. Simulation Conditions**

<b>Input Power</b>	1.3W
<b>Test Board (PCB)</b>	2L (1S1P) / 4L (2S2P)
<b>Control Condition</b>	Air Flow = 0, 1, 2 m/s

### 12.3.4. Thermal Performance of E-Pad LQFP 128-Pin on PCB under Still Air Convection

**Table 38. Thermal Performance of E-Pad LQFP 128-Pin on PCB under Still Air Convection**

	$\theta_{JA}$	$\theta_{JB}$	$\theta_{JC}$	$\Psi_{JB}$
2L PCB	24.06	10.92	12.09	10.95
4L PCB	21.32	10.80	11.74	9.78

Note:

$\theta_{JA}$ : Junction to ambient thermal resistance

$\theta_{JB}$ : Junction to board thermal resistance

$\theta_{JC}$ : Junction to case thermal resistance

$\Psi_{JB}$ : Junction to bottom surface center of PCB thermal characterization

### 12.3.5. Thermal Performance of E-Pad LQFP 128-Pin on PCB under Forced Convection

**Table 39. Thermal Performance of E-Pad LQFP 128-Pin on PCB under Forced Convection**

	Air Flow (m/s)	0	1	2
2L PCB	$\theta_{JA}$	24.06	20.70	19.86
	$\Psi_{JB}$	10.95	11.02	11.07
4L PCB	$\theta_{JA}$	21.32	18.21	17.44
	$\Psi_{JB}$	9.78	9.78	9.81

Note:

$\theta_{JA}$ : Junction to ambient thermal resistance

$\Psi_{JB}$ : Junction to bottom surface center of PCB thermal characterization

## 12.4. DC Characteristics

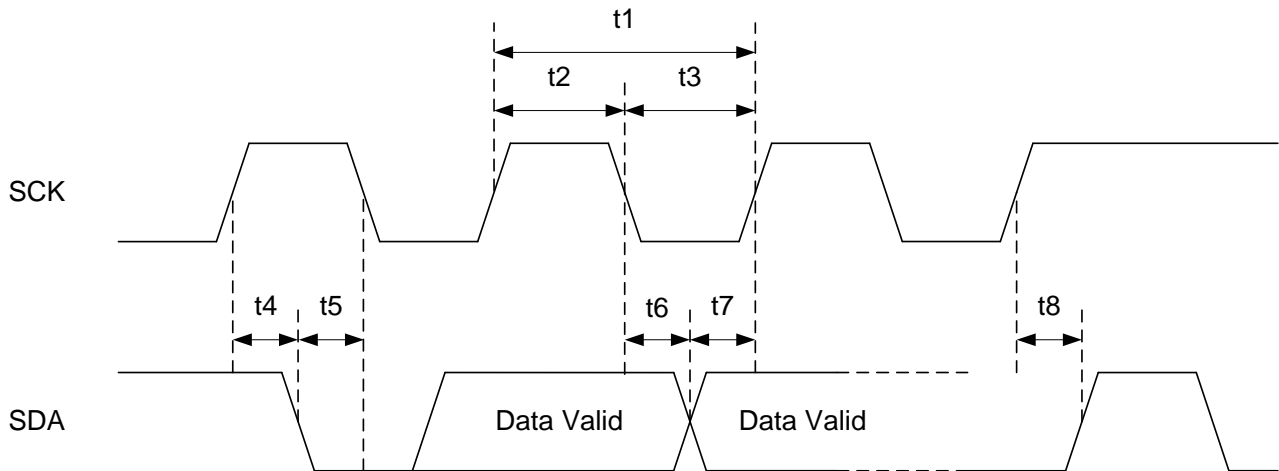
**Table 40. DC Characteristics**

Parameter	SYM	Min	Typ.	Max	Units
Power Supply Current for RGMII DVDDIO_1 (3.3V)	I <sub>DVDDIO_1</sub>	-	55	-	mA
Power Supply Current for Dual HSGMII SVDDH	I <sub>SVDDH</sub>	-	12	-	mA
Power Supply Current for Dual HSGMII SVDDL	I <sub>SVDDL_0</sub> , I <sub>SVDDL_1</sub>	-	89	-	mA
<b>System Idle (All UTP Port Link Down without LEDs)</b>					
Power Supply Current for VDDH	I <sub>DVDDIO</sub> , I <sub>AVDDH</sub>	-	18	-	mA
Power Supply Current for VDDL	I <sub>DVDDL</sub> , I <sub>AVDDL</sub> , I <sub>PLLVDL</sub>	-	76	-	mA
<b>1000M Active (All UTP Ports Link/Active without LEDs)</b>					
Power Supply Current for VDDH	I <sub>DVDDIO</sub> , I <sub>AVDDH</sub>	-	236	-	mA
Power Supply Current for VDDL	I <sub>DVDDL</sub> , I <sub>AVDDL</sub> , I <sub>PLLVDL</sub>	-	377	-	mA
<b>VDDIO=3.3V</b>					
TTL Input High Voltage	V <sub>ih</sub>	2.0	-	-	V
TTL Input Low Voltage	V <sub>il</sub>	-	-	0.7	V
Output High Voltage	V <sub>oh</sub>	2.7	-	-	V
Output Low Voltage	V <sub>ol</sub>	-	-	0.6	V
<b>VDDIO=2.5V</b>					
TTL Input High Voltage	V <sub>ih</sub>	1.7	-	-	V
TTL Input Low Voltage	V <sub>il</sub>	-	-	0.6	V
Output High Voltage	V <sub>oh</sub>	2.25	-	-	V
Output Low Voltage	V <sub>ol</sub>	-	-	0.4	V
<b>VDDIO=1.8V</b>					
TTL Input High Voltage	V <sub>ih</sub>	1.2	-	-	V
TTL Input Low Voltage	V <sub>il</sub>	-	-	0.6	V
Output High Voltage	V <sub>oh</sub>	1.45	-	-	V
Output Low Voltage	V <sub>ol</sub>	-	-	0.4	V

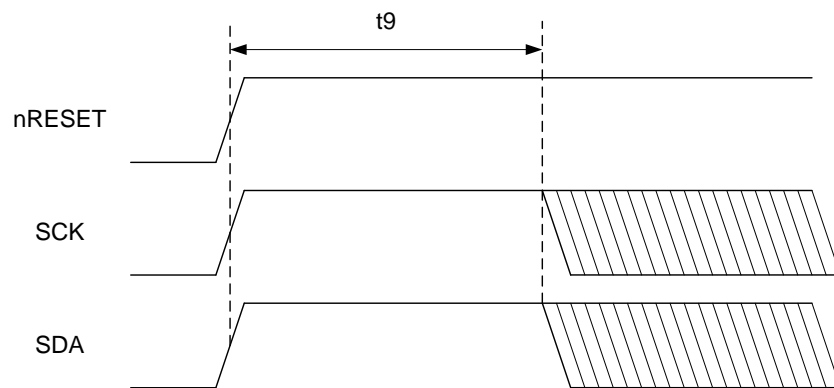
Note1: All test conditions are tested under 25 degrees Celsius.

## 12.5. AC Characteristics

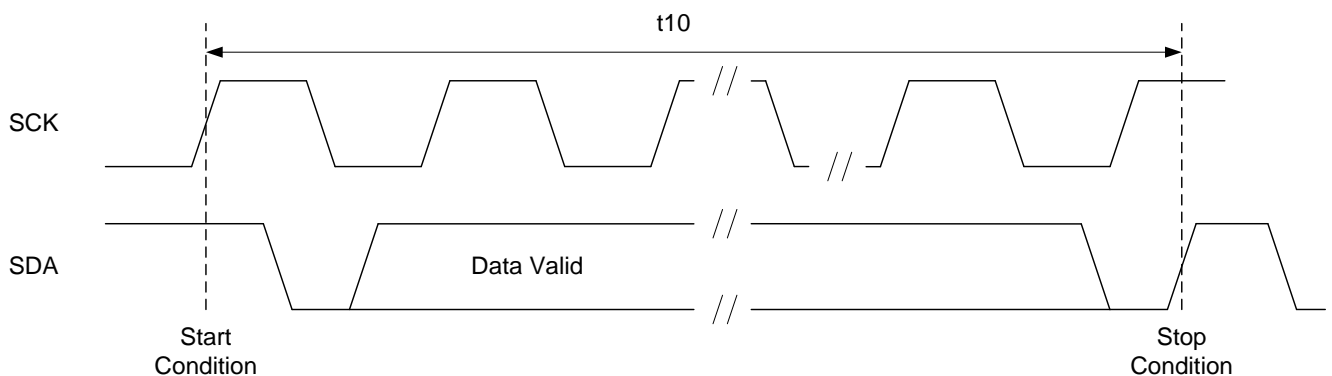
### 12.5.1. EEPROM SMI Host Mode Timing Characteristics



**Figure 19. EEPROM SMI Host Mode Timing Characteristics**



**Figure 20. SCK/SDA Power On Timing**

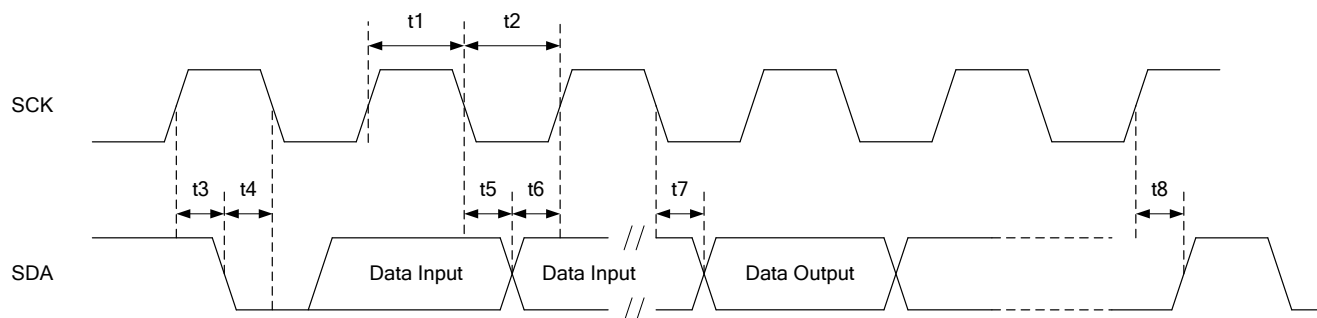


**Figure 21. EEPROM Auto-Load Timing**

**Table 41. EEPROM SMI Host Mode Timing Characteristics**

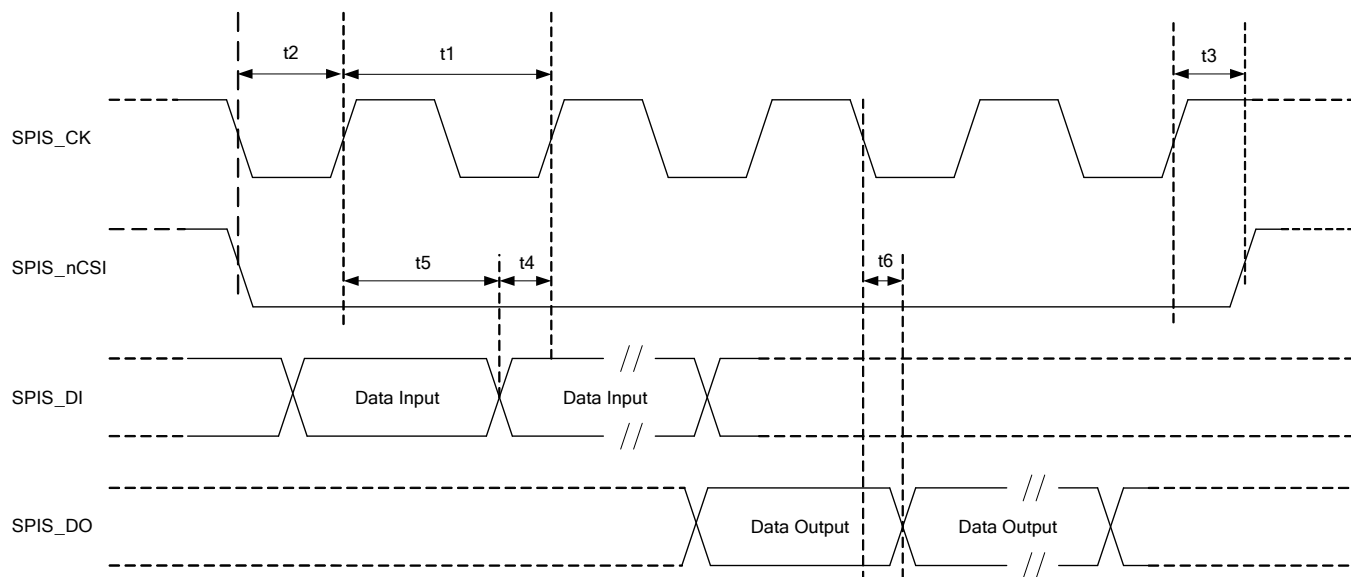
Symbol	Description	Type	Min	Typ.	Max	Units
t1	SCK Clock Period.	O	9.7	10	-	μs
t2	SCK High Time.	O	4.2	5	-	μs
t3	SCK Low Time.	O	4.2	5	-	μs
t4	START Condition Setup Time.	O	4.8	5.04	-	μs
t5	START Condition Hold Time.	O	4.8	4.96	-	μs
t6	Data Hold Time.	O	2.2	2.52	-	μs
t7	Data Setup Time.	O	2.2	2.48	-	μs
t8	STOP Condition Setup Time.	O	4.4	5.04	-	μs
t9	SCK/SDA Active from Reset Ready.	O	75	78.4	-	ms
t10	8K-bit EEPROM Auto-Load Time.	O	250	278	-	ms
-	SCK Rise Time (10% to 90%).	O	-	320	-	ns
-	SCK Fall Time (90% to 10%).	O	-	320	-	ns
-	Duty Cycle.	O	48.86	50	51.14	%

## 12.5.2. EEPROM SMI Slave Mode Timing Characteristics


**Figure 22. EEPROM SMI Slave Mode Timing Characteristics**
**Table 42. EEPROM SMI Slave Mode Timing Characteristics**

Symbol	Description	Type	Min	Typ.	Max	Units
t1	SCK High Time.	I	250	-	-	ns
t2	SCK Low Time.	I	250	-	-	ns
t3	START Condition Setup Time.	I	150	-	-	ns
t4	START Condition Hold Time.	I	150	-	-	ns
t5	Data Hold Time.	I	150	-	-	ns
t6	Data Setup Time.	I	150	-	-	ns
t7	Clock to Data Output Delay.	O	-	100	-	ns
t8	STOP Condition Setup Time.	I	150	-	-	ns

### 12.5.3. SPI Slave Mode Timing Characteristics



**Figure 23. SPI-Slave Mode Timing Characteristics**

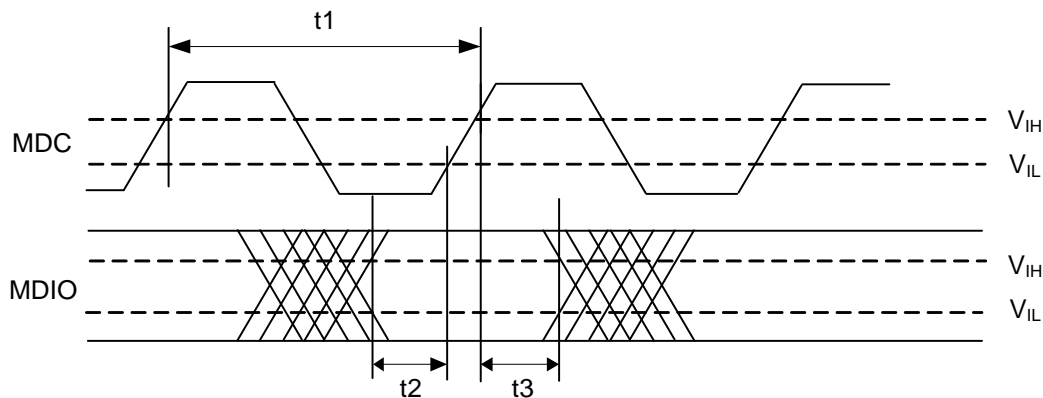
**Table 43. SPI-Slave Mode Timing Characteristics**

Symbol	Description	Type	Min	Typ.	Max	Units
t1	SPIS_CK Clock Period.	I	200	-	-	ns
t2	SPIS_nCSI Active Setup Time relative to SPIS_CK.	I	30	-	-	ns
t3	SPIS_nCSI Active Hold Time relative to SPIS_CK.	I	30	-	-	ns
t4	SPIS_DI to SPIS_CK Setup Time.	I	30	-	-	ns
t5	SPIS_DI to SPIS_CK Hold Time.	I	30	-	-	ns
t6	SPIS_CK Falling Edge to SPIS_DO Output Delay Time.	O	10	24	-	ns

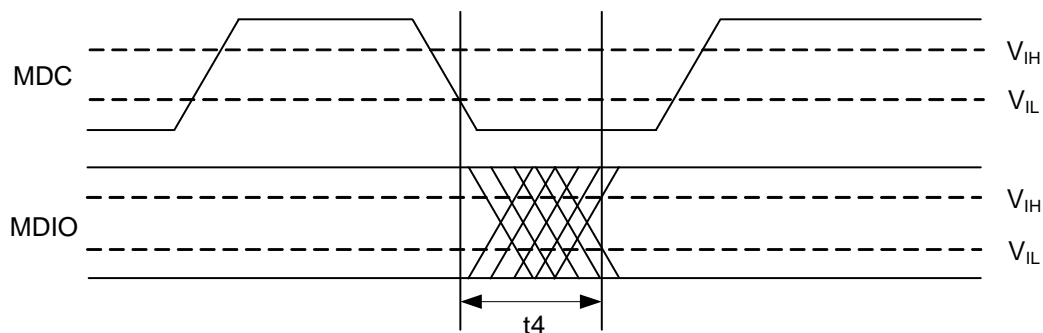
### 12.5.4. MDIO Slave Mode Timing Characteristics

The RTL8367SCI supports MDIO (MMD) slave mode. The Master (CPU) can access the Slave (RTL8367SCI) registers via the MDIO interface. The MDIO is a bi-directional signal that can be sourced by the Master or the Slave. In a write command, the master sources the MDIO signal. In a read command, the slave sources the MDIO signal.

- The timing characteristics  $t_1$ ,  $t_2$ , and  $t_3$  (Table 44) of the Master (the RTL8367SCI link partner CPU) are provided by the Master when the Master sources the MDIO signal (Write command)
- The timing characteristic  $t_4$  (Table 44) of the Slave (RTL8367SCI) are provided by the RTL8367SCI when the RTL8367SCI sources the MDIO signal (Read command)



**Figure 24. MDIO Sourced by Master**



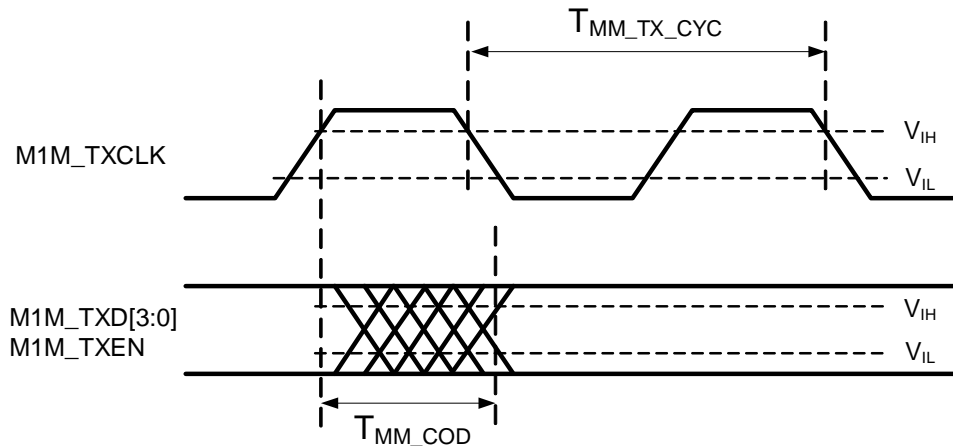
**Figure 25. MDIO Sourced by RTL8367SCI (Slave)**

**Table 44. MDIO Timing Characteristics and Requirement**

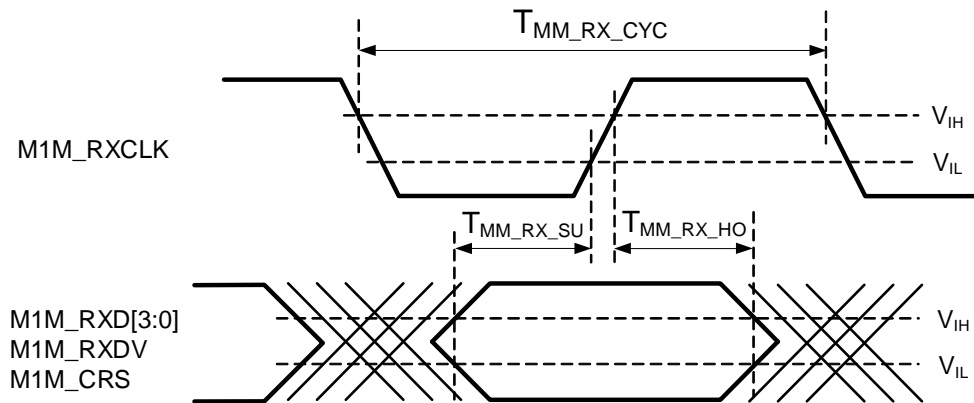
Parameter	SYM	Description/Condition	Type	Min	Typ.	Max	Units
MDC Clock Period	$t_1$	Clock Period.	I	125	-	-	ns
MDIO to MDC Rising Setup Time (Write Data)	$t_2$	Input Setup Time.	I	25	-	-	ns
MDIO to MDC Rising Hold Time (Write Data)	$t_3$	Input Hold Time.	I	25	-	-	ns
MDC to MDIO Delay Time (Read Data)	$t_4$	Clock (Falling Edge) to Data Delay Time.	O	0	2.8	40	ns



### 12.5.5. MII MAC Mode Timing



**Figure 26. MII MAC Mode Clock to Data Output Delay Timing**

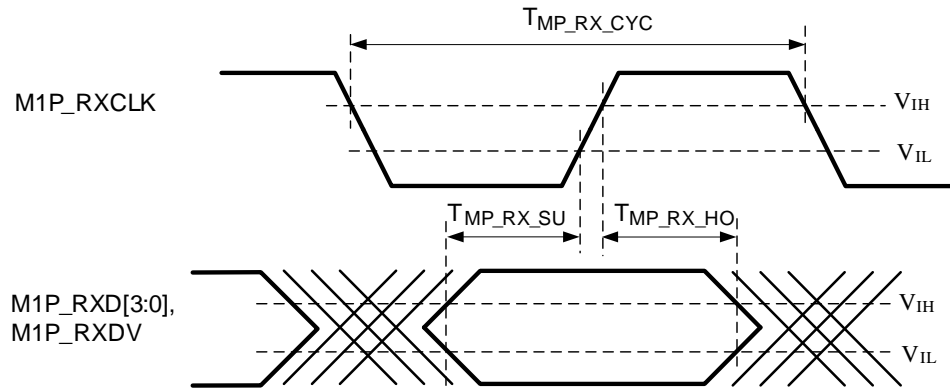


**Figure 27. MII MAC Mode Input Timing**

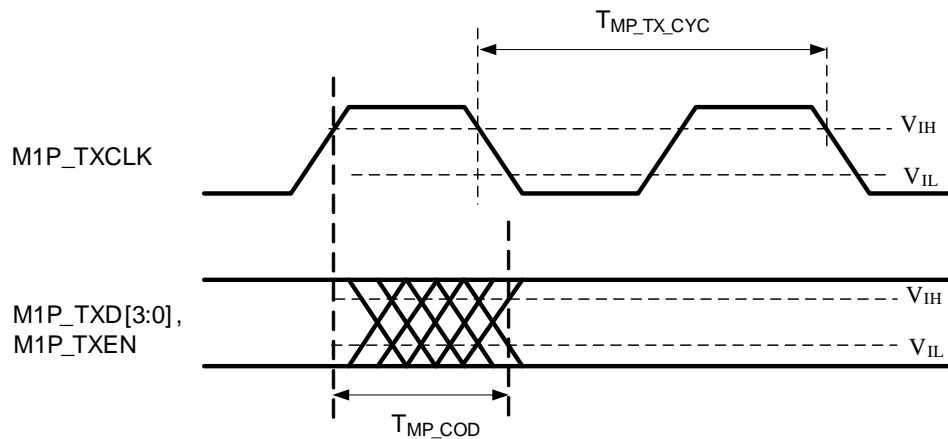
**Table 45. MII MAC Mode Timing**

Parameter	SYM	Description/Condition	Type	Min	Typ.	Max	Units
100Base-TX M1M_TXCLK and M1M_RXCLK Input Cycle Time	$T_{MM\_TX\_CYC}$ $T_{MM\_RX\_CYC}$	25MHz Clock Input.	I	-	40	-	ns
10Base-T M1M_TXCLK and M1M_RXCLK Input Cycle Time	$T_{MM\_TX\_CYC}$ $T_{MM\_RX\_CYC}$	2.5MHz Clock Input.	I	-	400	-	ns
M1M_TXCLK to M1M_TXD[3:0] and M1M_TXEN Output Delay Time	$T_{MM\_COD}$	-	O	3	5	7	ns
M1M_RXD[3:0], M1M_RXDV, and M1M_CRS Input Setup Time	$T_{MM\_RX\_SU}$	-	I	10	-	-	ns
M1M_RXD[3:0], M1M_RXDV, and M1M_CRS Input Hold Time	$T_{MM\_RX\_HO}$	-	I	10	-	-	ns

### 12.5.6. MII PHY Mode Timing



**Figure 28. MII PHY Mode Output Timing**

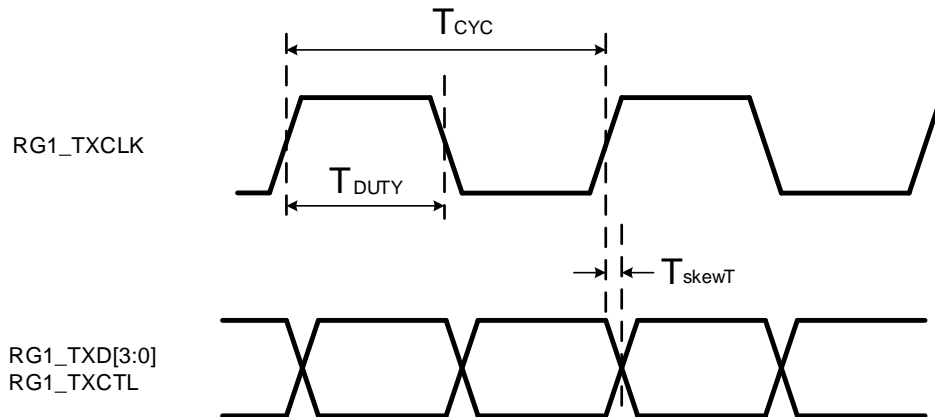


**Figure 29. MII PHY Mode Clock Output to Data Input Delay Timing**

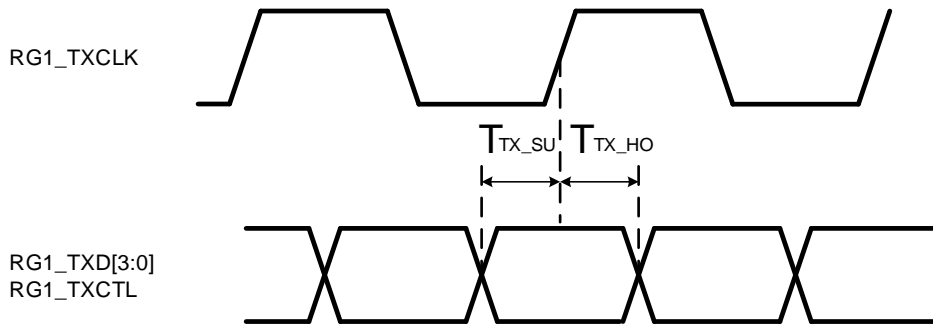
**Table 46. MII PHY Mode Timing Characteristics**

Parameter	SYM	Description/Condition	Type	Min	Typ.	Max	Units
100M M1P_RXCLK and M1P_TXCLK Output Cycle Time	$T_{MP\_RX\_CYC}$ $T_{MP\_TX\_CYC}$	25MHz Clock Output.	O	-	40	-	ns
10M M1P_RXCLK and M1P_TXCLK Output Cycle Time	$T_{MP\_RX\_CYC}$ $T_{MP\_TX\_CYC}$	2.5MHz Clock Output.	O	-	400	-	ns
100M M1P_RXD[3:0] and M1P_RXDV to M1P_RXCLK Output Setup Time	$T_{MP\_RX\_SU}$	-	O	14	18	-	ns
100M M1P_RXD[3:0] and M1P_RXDV to M1P_RXCLK Output Hold Time	$T_{MP\_RX\_HO}$	-	O	16	19.5	-	ns
100M M1P_TXCLK Clock Output to M1P_TXD[3:0] and M1P_TXEN Input Delay Time	$T_{MP\_COD}$	-	I	0	-	25	ns

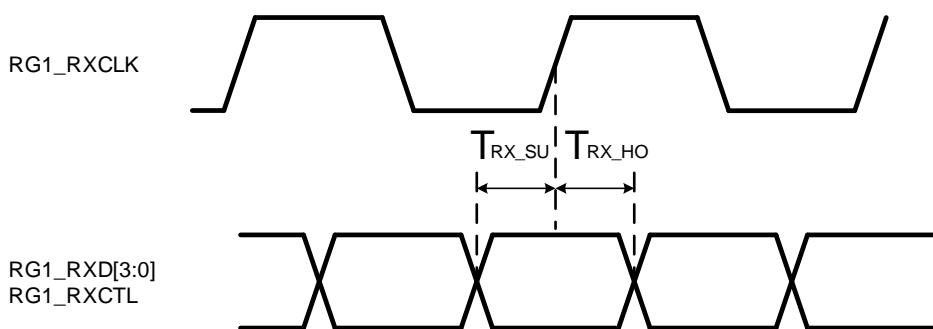
### 12.5.7. RGMII Timing Characteristics



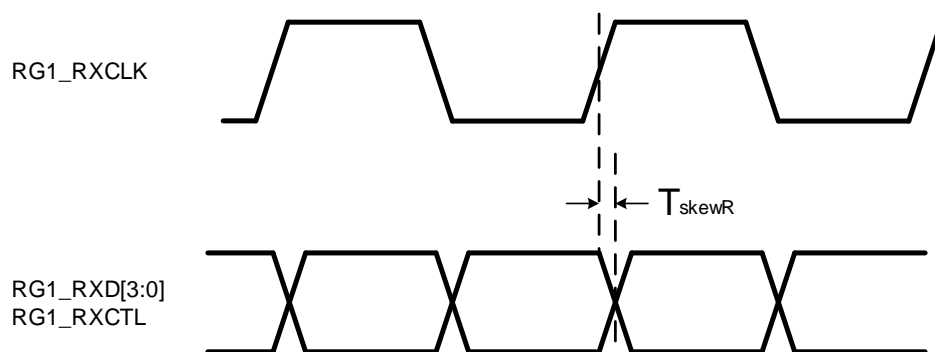
**Figure 30. RGMII Output Timing Characteristics ( $RG1\_TXCLK\_DELAY=0$ )**



**Figure 31. RGMII Output Timing Characteristics ( $RG1\_TXCLK\_DELAY=2ns$ )**



**Figure 32. RGMII Input Timing Characteristics ( $RG1\_RXCLK\_DELAY=0$ )**



**Figure 33. RGMII Input Timing Characteristics (RG1\_RXCLK\_DELAY=2ns)**

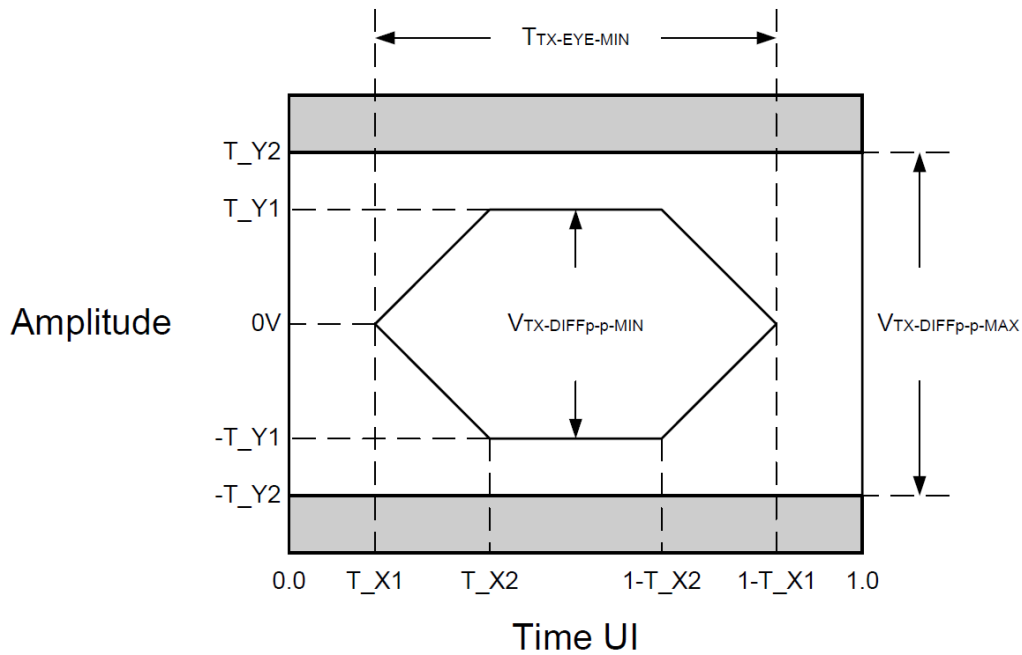
**Table 47. RGMII Timing Characteristics**

Parameter	SYM	Description/Condition	Type	Min	Typ.	Max	Units
1000M RG1_TXCLKc Output Cycle Time	T <sub>TX_CYC</sub>	125MHz Clock Output. Refer to Figure 30	O	7.6	8	8.6	ns
100M RG1_TXCLK Output Cycle Time	T <sub>TX_CYC</sub>	25MHz Clock Output. Refer to Figure 30	O	38	40	42	ns
10M RG1_TXCLK Output Cycle Time	T <sub>TX_CYC</sub>	2.5MHz Clock Output. Refer to Figure 30	O	380	400	420	ns
RG1_TXD[3:0] and RG1_TXCTL to RG1_TXCLK Output Skew	T <sub>skewT</sub>	Disable Output Clock Delay. (RG1_TXCLK_DELAY=0). Refer to Figure 30	O	-500	-	500	ps
RG1_TXD[3:0] and RG1_TXCTL to RG1_TXCLK Output Setup Time	T <sub>TX_SU</sub>	Enable Output Clock Delay. (RG1_TXCLK_DELAY=1). Refer to Figure 31	O	1.2	-	-	ns
RG1_TXD[3:0] and RG1_TXCTL to RG1_TXCLK Output Hold Time	T <sub>TX_HO</sub>	Enable Output Clock Delay. (RG1_TXCLK_DELAY=1). Refer to Figure 31	O	1.2	-	-	ns
RG1_RXD[3:0] and RG1_RXCTL to RG1_RXCLK Input Setup Time	T <sub>RX_SU</sub>	Disable Input Clock Delay. (RG1_RXCLK_DELAY=0). Refer to Figure 32	I	1.0	-	-	ns
RG1_RXD[3:0] and RG1_RXCTL to RG1_RXCLK Input Hold Time	T <sub>RX_HO</sub>	Disable Input Clock Delay. (RG1_RXCLK_DELAY=0). Refer to Figure 32	I	1.0	-	-	ns
RG1_RXD[3:0] and RG1_RXCTL to RG1_RXCLK Input Skew	T <sub>skewR</sub>	Enable Input Clock Delay. (RG1_RXCLK_DELAY=1). Refer to Figure 33	I	-600	-	600	ps

## 12.5.8. HSGMII Characteristics

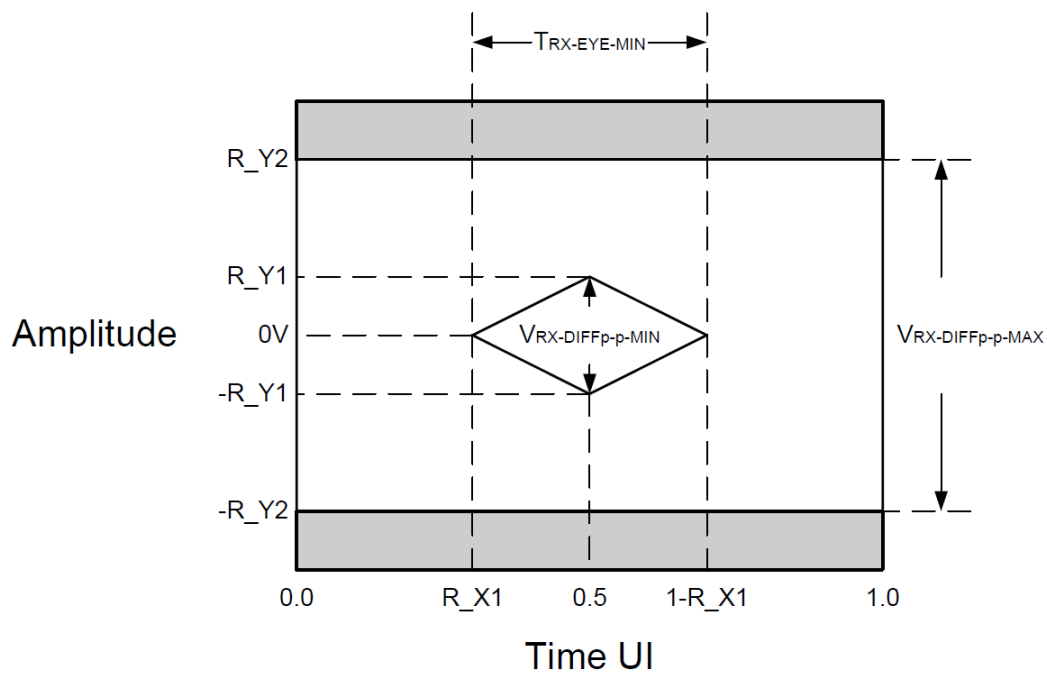
**Table 48. HSGMII Differential Transmitter Characteristics**

Parameter		SYM	Min	Typ.	Max	Units	Notes
Unit Interval		UI	319.968	320	320.032	ps	320ps $\pm$ 100ppm
Eye Mask		T_X1	-	-	0.175	UI	-
Eye Mask		T_X2	-	-	0.39	UI	-
Eye Mask		T_Y1	400	-	-	mV	-
Eye Mask		T_Y2	-	-	800	mV	-
Output Differential Voltage		V <sub>TX-DIFFp-p</sub>	500	700	1000	mV	-
Output Jitter	TJ	T <sub>TX-JITTER</sub>	-	-	0.3	UI	T <sub>TX-JITTER-MAX</sub> = 1 - T <sub>TX-EYE-MIN</sub> = 0.30UI
	DJ		-	-	0.165	UI	
Minimum TX Eye Width		T <sub>TX-EYE</sub>	0.65	-	-	UI	-
Output Rise Time		T <sub>TX-RISE</sub>	0.125	-	-	UI	20% ~ 80%
Output Fall Time		T <sub>TX-FALL</sub>	0.125	-	-	UI	20% ~ 80%
Differential Resistance		R <sub>TX</sub>	80	100	120	ohm	-
AC Coupling Capacitor		C <sub>TX</sub>	80	100	120	nF	-
Transmit Length in PCB		L <sub>TX</sub>	-	-	10	inch	-


**Figure 34. HSGMII Differential Transmitter Eye Diagram**

**Table 49. HSGMII Differential Receiver Characteristics**

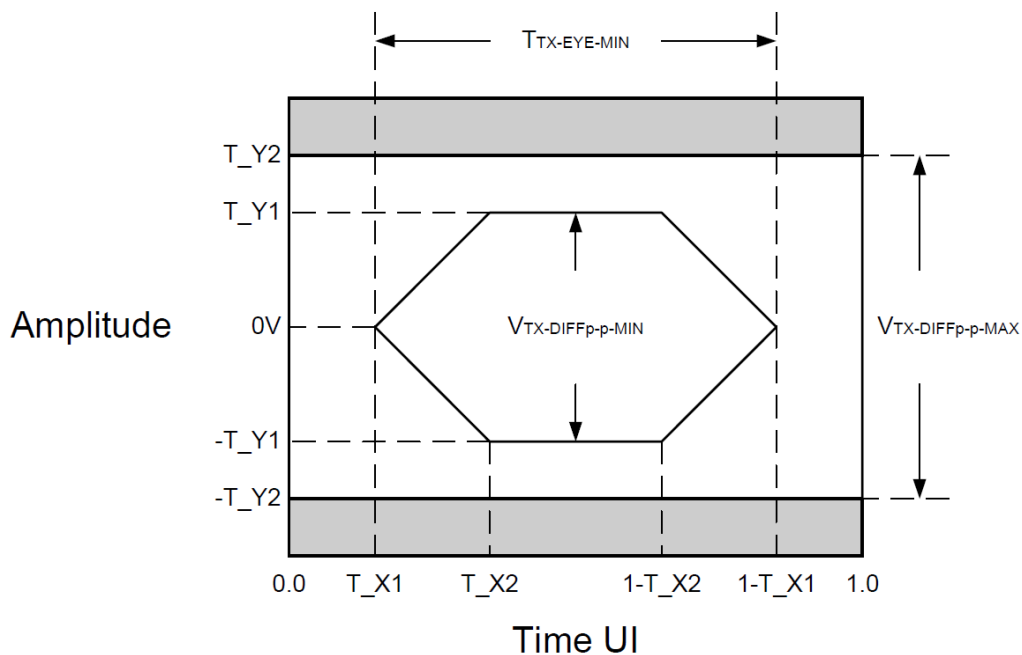
Parameter	SYM	Min	Typ.	Max	Units	Notes
Unit Interval	UI	319.968	320	320.032	ps	$320\text{ps} \pm 100\text{ppm}$
Eye Mask	R_X1	-	-	0.275	UI	-
Eye Mask	R_Y1	100	-	-	mV	-
Eye Mask	R_Y2	-	-	800	mV	-
Input Differential Voltage	$V_{RX-DIFFp-p}$	200	-	1200	mV	-
Minimum RX Eye Width	$T_{RX-EYE}$	0.4	-	-	UI	-
Input Jitter Tolerance	$T_{RX-JITTER}$	-	-	0.6	UI	$T_{RX-JITTER-MAX}$ $= 1 - T_{RX-EYE-MIN}$ $= 0.6\text{UI}$
Differential Resistance	$R_{RX}$	80	100	120	ohm	-


**Figure 35. HSGMII Differential Receiver Eye Diagram**

## 12.5.9. SGMII Characteristics

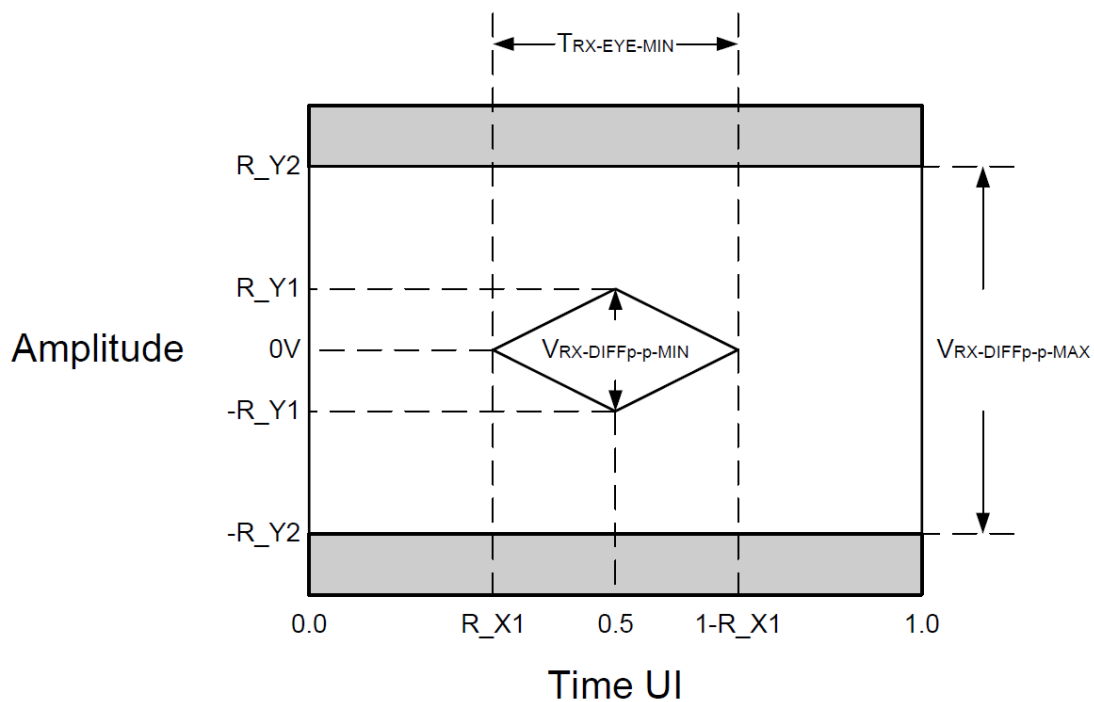
**Table 50. SGMII Differential Transmitter Characteristics**

Parameter	SYM	Min	Typ.	Max	Units	Notes
Unit Interval	UI	799.92	800	800.08	ps	800ps $\pm$ 100ppm
Eye Mask	T_X1	-	-	0.15	UI	-
Eye Mask	T_X2	-	-	0.4	UI	-
Eye Mask	T_Y1	150	-	-	mV	-
Eye Mask	T_Y2	-	-	400	mV	-
Output Differential Voltage	V <sub>TX-DIFFp-p</sub>	300	700	800	mV	-
Minimum TX Eye Width	T <sub>TX-EYE</sub>	0.7	-	-	UI	-
Output Jitter	T <sub>TX-JITTER</sub>	-	-	0.3	UI	T <sub>TX-JITTER-MAX</sub> = 1 - T <sub>TX-EYE-MIN</sub> = 0.30UI
Data dependent jitter	-	-	70	-	ps	-
Output Rise Time	T <sub>TX-RISE</sub>	100	-	200	ps	20% ~ 80%
Output Fall Time	T <sub>TX-FALL</sub>	100	-	200	ps	20% ~ 80%
Output impedance	R <sub>TX</sub>	40	-	140	ohm	single-end
AC Coupling Capacitor	C <sub>TX</sub>	80	100	120	nF	-
Transmit Length in PCB	L <sub>TX</sub>	-	-	10	inch	-


**Figure 36. SGMII Differential Transmitter Eye Diagram**

**Table 51. SGMII Differential Receiver Characteristics**

Parameter	SYM	Min	Typ.	Max	Units	Notes
Unit Interval	UI	799.92	800	800.08	ps	800ps $\pm$ 100ppm
Eye Mask	R_X1	-	-	0.15	UI	-
Eye Mask	R_Y1	100	-	-	mV	-
Eye Mask	R_Y2	-	-	600	mV	-
Input Differential Voltage	V <sub>RX-DIFFp-p</sub>	200	-	1200	mV	-
Minimum RX Eye Width	T <sub>RX-EYE</sub>	0.4	-	-	UI	-
Input Jitter Tolerance	T <sub>RX-JITTER</sub>	-	-	0.6	UI	T <sub>RX-JITTER-MAX</sub> = 1 - T <sub>RX-EYE-MIN</sub> = 0.6UI
Differential Resistance	R <sub>RX</sub>	80	100	120	ohm	-

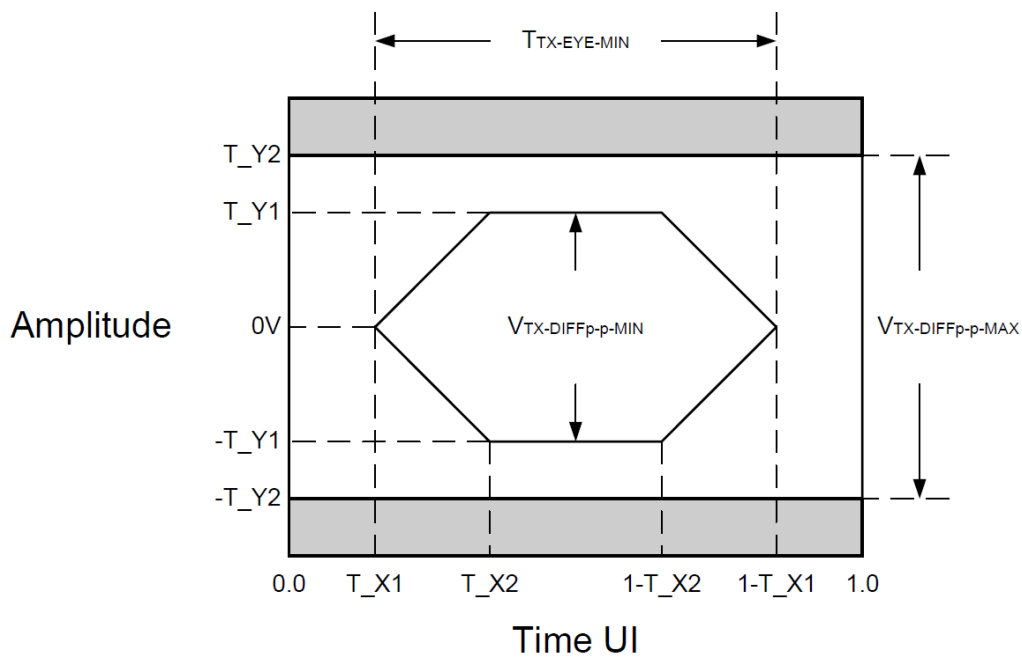

**Figure 37. SGMII Differential Receiver Eye Diagram**



## 12.5.10. 1000Base-X Characteristics

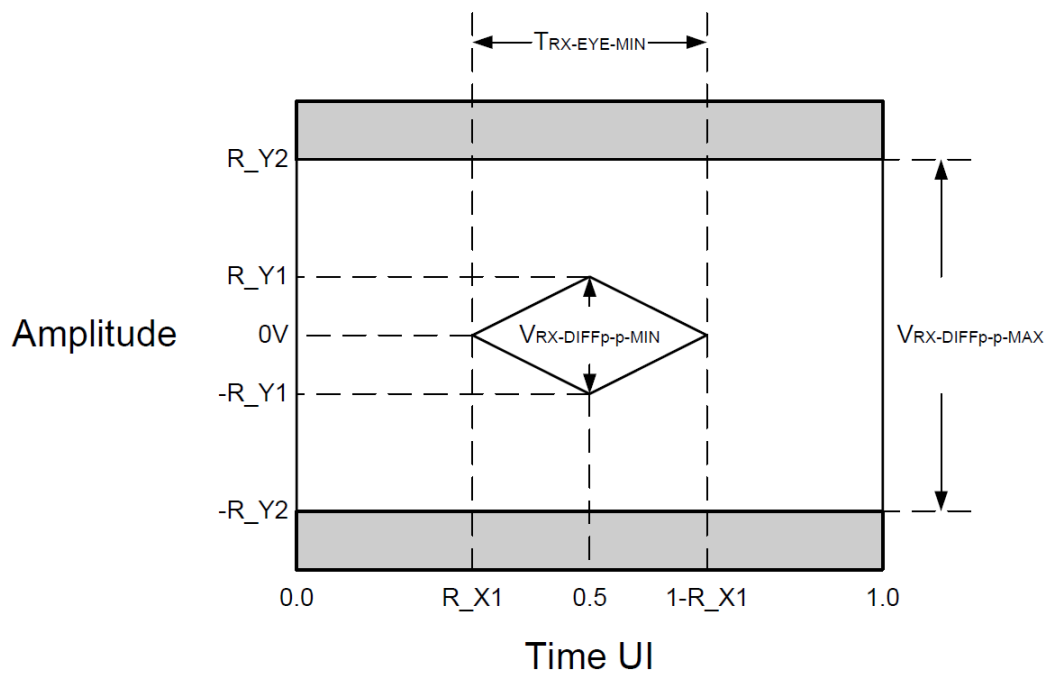
**Table 52. 1000Base-X Differential Transmitter Characteristics**

Parameter	SYM	Min	Typ.	Max	Units	Notes
Unit Interval	UI	799.76	800	800.24	ps	800ps $\pm$ 300ppm
Eye Mask	T_X1	-	-	0.15	UI	-
Eye Mask	T_X2	-	-	0.4	UI	-
Eye Mask	T_Y1	250	-	-	mV	-
Eye Mask	T_Y2	-	-	600	mV	-
Output Differential Voltage	V <sub>TX-DIFFp-p</sub>	500	700	1200	mV	-
Minimum TX Eye Width	T <sub>TX-EYE</sub>	0.7	-	-	UI	-
Output Jitter	T <sub>TX-JITTER</sub>	-	-	0.3	UI	T <sub>TX-JITTER-MAX</sub> = 1 - T <sub>TX-EYE-MIN</sub> = 0.3UI
Output Rise Time	T <sub>TX-RISE</sub>	0.075	-	-	UI	20% ~ 80%
Output Fall Time	T <sub>TX-FALL</sub>	0.075	-	-	UI	20% ~ 80%
Differential Resistance	R <sub>TX</sub>	80	100	120	ohm	-
AC Coupling Capacitor	C <sub>TX</sub>	80	100	120	nF	-
Transmit Length in PCB	L <sub>TX</sub>	-	-	10	inch	-


**Figure 38. 1000Base-X Differential Transmitter Eye Diagram**

**Table 53. 1000Base-X Differential Receiver Characteristics**

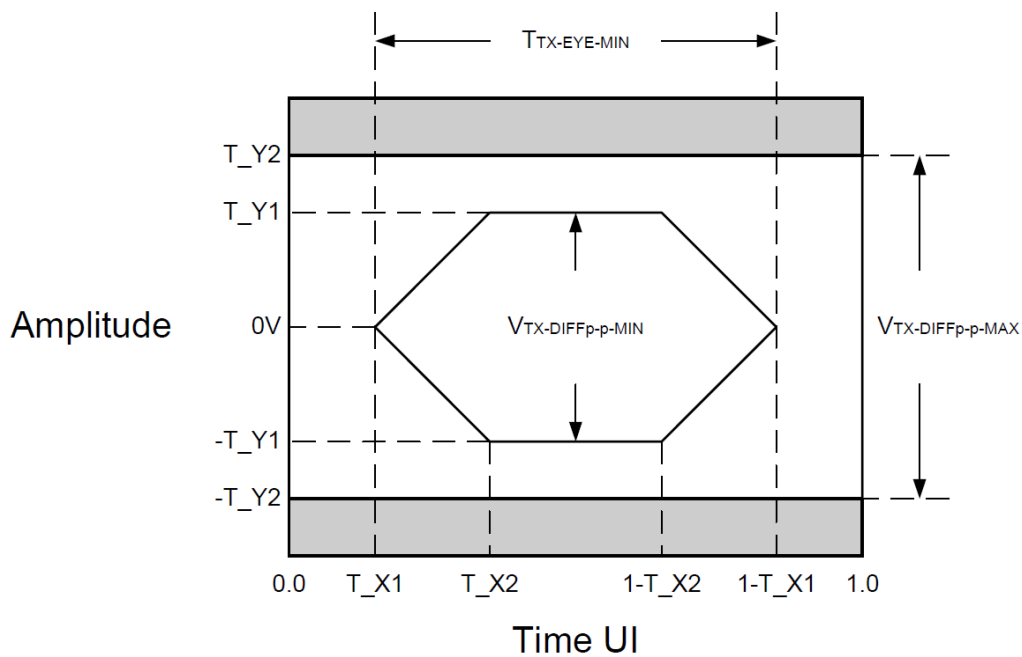
Parameter	SYM	Min	Typ.	Max	Units	Notes
Unit Interval	UI	799.76	800	800.24	ps	$\pm 300\text{ppm}$
Eye Mask	R_X1	-	-	0.3	UI	-
Eye Mask	R_Y1	185	-	-	mV	-
Eye Mask	R_Y2	-	-	1000	mV	-
Input Differential Voltage	$V_{RX-DIFFp-p}$	370	-	2000	mV	-
Minimum RX Eye Width	$T_{RX-EYE}$	0.4	-	-	UI	-
Input Jitter Tolerance	$T_{RX-JITTER}$	-	-	0.6	UI	$T_{RX-JITTER-MAX}$ $= 1 - T_{RX-EYE-MIN}$ $= 0.6\text{UI}$
Differential Resistance	$R_{RX}$	80	100	120	ohm	-


**Figure 39. 1000Base-X Differential Receiver Eye Diagram**

## 12.5.11. 100Base-FX Characteristics

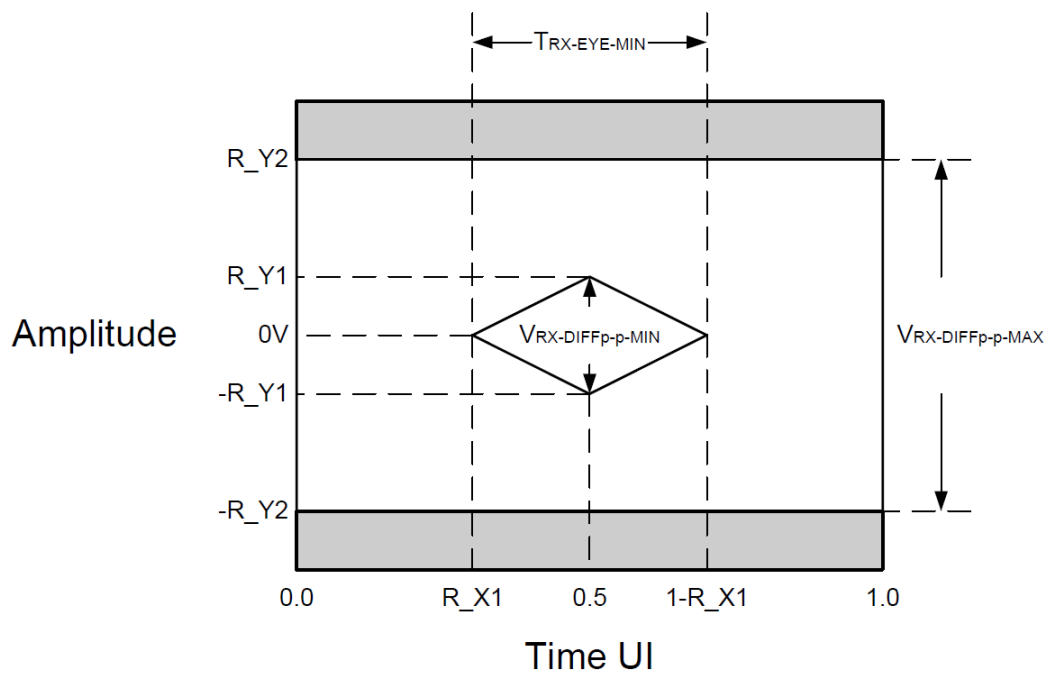
**Table 54. 100Base-FX Differential Transmitter Characteristics**

Parameter	SYM	Min	Typ.	Max	Units	Notes
Unit Interval	UI	7.9976	8	8.0024	ns	8ns ± 300ppm
Eye Mask	T_X1	-	-	0.15	UI	-
Eye Mask	T_X2	-	-	0.4	UI	-
Eye Mask	T_Y1	250	-	-	mV	-
Eye Mask	T_Y2	-	-	600	mV	-
Output Differential Voltage	V <sub>TX-DIFFp-p</sub>	500	700	1200	mV	-
Minimum TX Eye Width	T <sub>TX-EYE</sub>	0.7	-	-	UI	-
Output Jitter	T <sub>TX-JITTER</sub>	-	-	0.3	UI	T <sub>TX-JITTER-MAX</sub> = 1 - T <sub>TX-EYE-MIN</sub> = 0.3UI
Output Rise Time	T <sub>TX-RISE</sub>	0.0075	-	-	UI	20% ~ 80%
Output Fall Time	T <sub>TX-FALL</sub>	0.0075	-	-	UI	20% ~ 80%
Differential Resistance	R <sub>TX</sub>	80	100	120	ohm	-
AC Coupling Capacitor	C <sub>TX</sub>	80	100	120	nF	-
Transmit Length in PCB	L <sub>TX</sub>	-	-	10	inch	-


**Figure 40. 100Base-FX Differential Transmitter Eye Diagram**

**Table 55. 100Base-FX Differential Receiver Characteristics**

Parameter	SYM	Min	Typ.	Max	Units	Notes
Unit Interval	UI	7.9976	8	8.0024	ns	$8\text{ns} \pm 300\text{ppm}$
Eye Mask	R_X1	-	-	0.3	UI	-
Eye Mask	R_Y1	185	-	-	mV	-
Eye Mask	R_Y2	-	-	1000	mV	-
Input Differential Voltage	$V_{RX-DIFFp-p}$	370	-	2000	mV	-
Minimum RX Eye Width	$T_{RX-EYE}$	0.4	-	-	UI	-
Input Jitter Tolerance	$T_{RX-JITTER}$	-	-	0.6	UI	$T_{RX-JITTER-MAX}$ $= 1 - T_{RX-EYE-MIN}$ $= 0.6\text{UI}$
Differential Resistance	$R_{RX}$	80	100	120	ohm	-


**Figure 41. 100Base-FX Differential Receiver Eye Diagram**

## 12.6. Power and Reset Characteristics

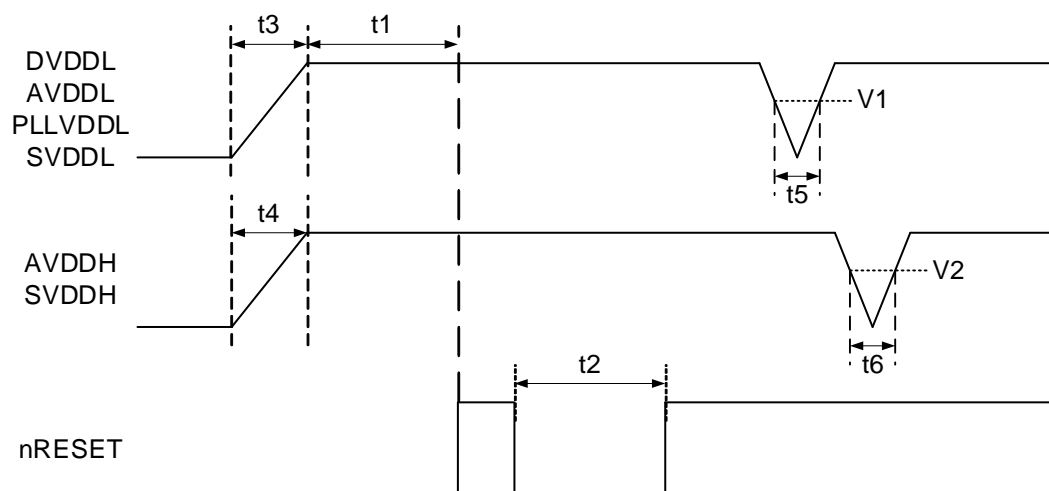


Figure 42. Power and Reset Characteristics

Table 56. Power and Reset Timing Requirements

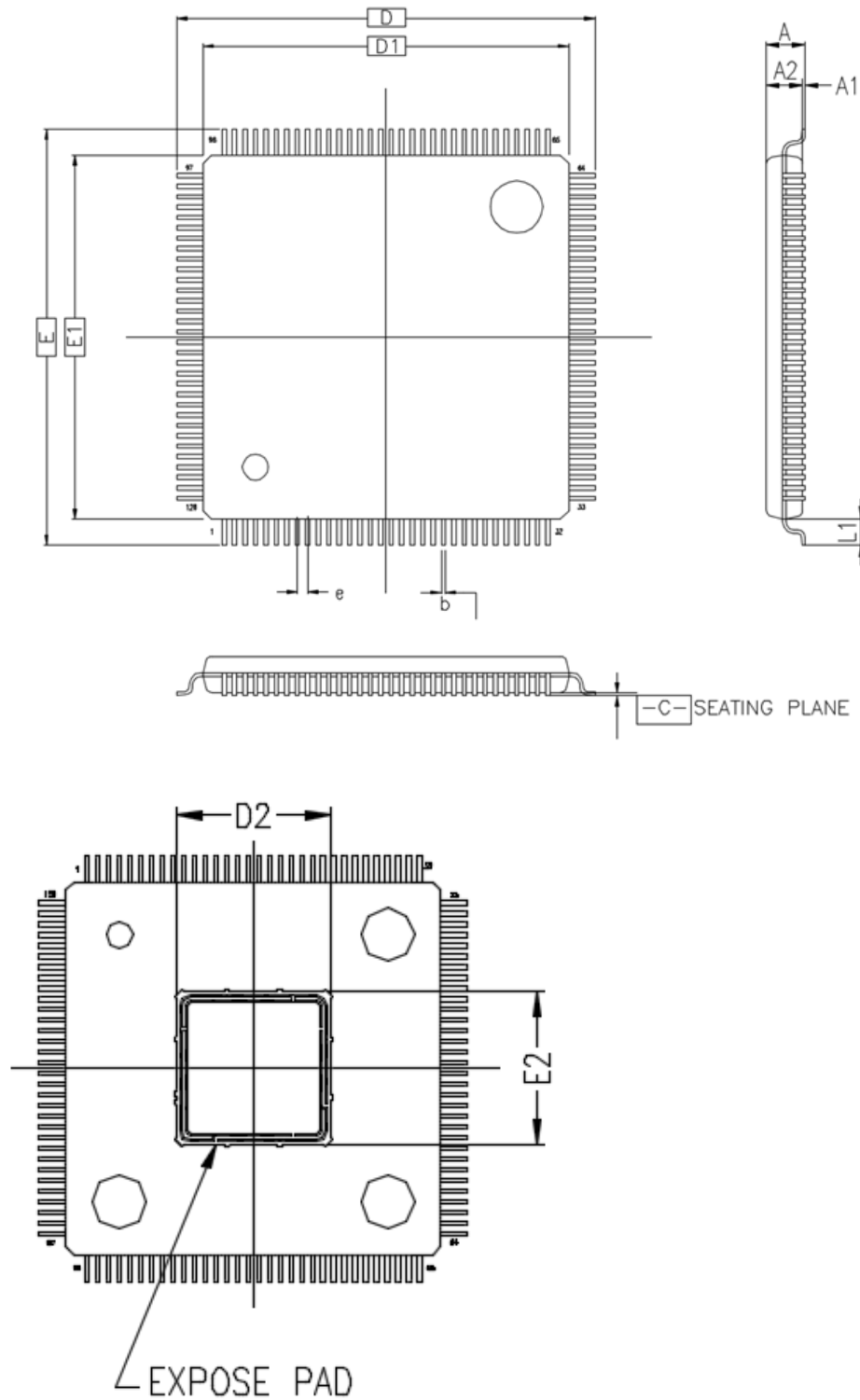
Parameter	SYM	Description/Condition	Type	Min	Typ.	Max	Units
Reset Delay Time	t1	The duration from 'all power steady' to the reset signal released to high.	I	0	-	-	ms
Reset Low Time	t2	The duration of reset signal remaining low time before issuing a reset to the RTL8367SC.	I	10	-	-	ms
VDDL Power Rise Time	t3	DVDDL, AVDDL, PLLVDDL, and SVDDL power rise time. (10% ~ 90%)	I	0.5	-	10	ms
VDDH Power Rise Time	t4	AVDDH and SVDDH power rise time. (10% ~ 90%)	I	0.5	-	10	ms

Table 57. Power Monitor Reset Characteristics

Parameter	SYM	Description/Condition	Type	Min	Typ.	Max	Units
Duration of VDDL power monitor reset	t5	The duration to issue power monitor reset when VDDL voltage drop lower than voltage threshold V1.	I	0.2	-	-	μs
Duration of VDDH power monitor reset	t6	The duration to issue power monitor reset when VDDH voltage drop lower than voltage threshold V2.	I	0.2	-	-	μs
Voltage drop threshold of VDDL power monitor reset	V1	The VDDL voltage drop threshold to issue power monitor reset.	I	0.5	-	0.945	V
Voltage drop threshold of VDDH power monitor reset	V2	The VDDH voltage drop threshold to issue power monitor reset.	I	1.65	-	2.97	V

## 13. Mechanical Dimensions

Thermally Enhanced Low Profile Plastic Quad Flat Package 128 Leads 14x14mm<sup>2</sup> Outline.



Symbol	Dimension in mm			Dimension in inch		
	Min	Nom	Max	Min	Nom	Max
A	1.40	1.50	1.60	0.055	0.059	0.063
A <sub>1</sub>	0.05	0.10	0.15	0.002	0.004	0.006
A <sub>2</sub>	1.35	1.40	1.45	0.053	0.055	0.057
b	0.13	0.16	0.23	0.005	0.006	0.009
D/E	16.00 BSC			0.630 BSC		
D <sub>1</sub> /E <sub>1</sub>	14.00 BSC			0.551 BSC		
D <sub>2</sub> /E <sub>2</sub>	5.46	5.72	5.97	0.215	0.225	0.235
e	0.40 BSC			0.016 BSC		
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		

Notes:

1. CONTROLLING DIMENSION: MILLIMETER(mm)
2. A<sub>1</sub>: E-PAD STAND OFF
3. REFERENCE DOCUMENT: JEDEC MS-026

## 14. Ordering Information

**Table 58. Ordering Information**

Part Number	Package
RTL8367SCI-CG	E-pad LQFP 128-pin 'Green' Package. Industrial grade.

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